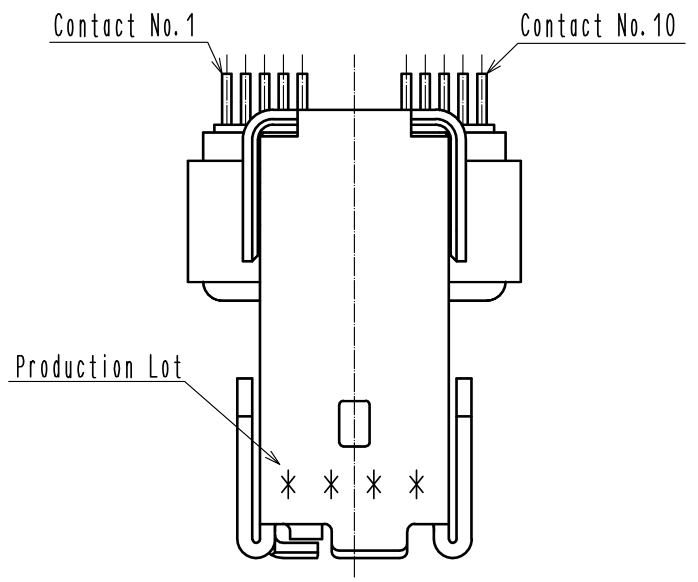
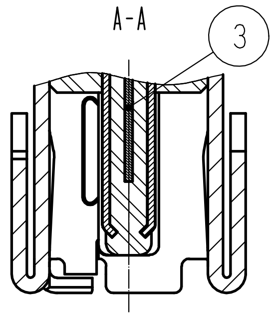
2019/12/24 12:59:24(JST) KH.OGAWA

RoHS2(10 substances conformity)
参考図：ご確認用。正式には別途納入仕様書をご請求願います。
本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。





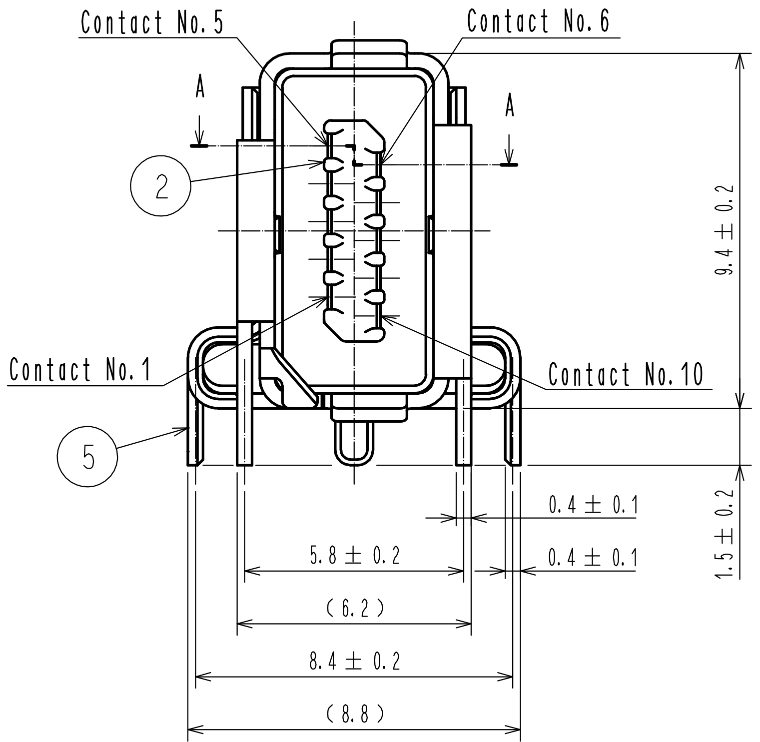
Notes. 1 Co-planarity is within 0.1 mm.

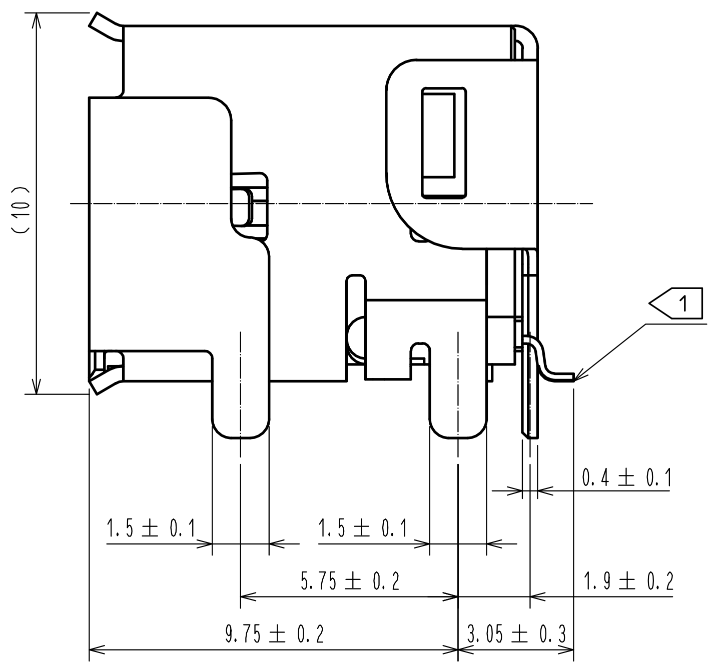
2. As for part No.5 the performance remains good even if there are rubbing wounds by the assembly process.
And the perfomance remains good though there might be a difference inthe pating luster beteween each plating lots.

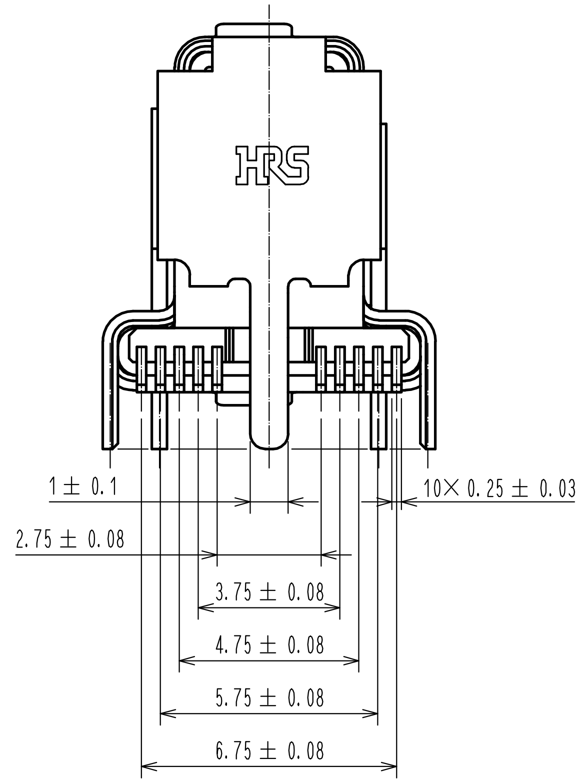
3 Per reel : 400 pcs.

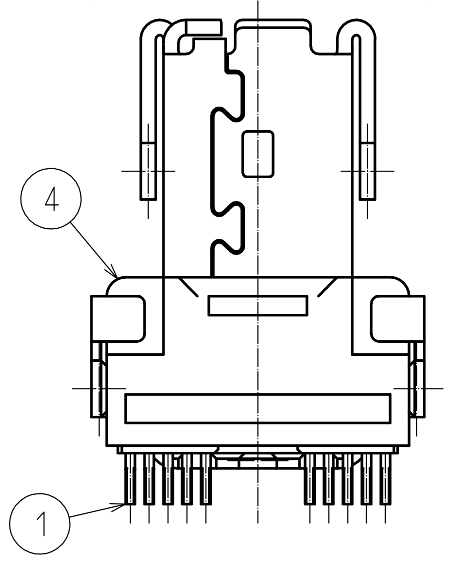
4 Refer to the mated condition diagram for the panel thickness and layout.

5. This produt is mounted by reflow soldering.
Refer to specification sheet ELC-129430-01-00 for reflow soldering.









NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
3	Stainless Steel		7	PE	
2	LCP	Gray、UL94V-0	6	PS	
1	Copper Alloy	Contact area : Palladium-Nickel 0.75 μm min. + Gold 0.05 μm min. Wiring area : Gold 0.03 μm min. Under plating : Nickel 2 μm min.	5	Stainless Steel	Surface : Tin 1 μm min. Under plating : Nickel 0.2 μm min.
			4	LCP	Gray、UL94V-0

UNITS		SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm		5 : 1	5	1	DIS-E-00002758	MT. YASUDA	KI. NAGANUMA	20191219

HIROSE
ELECTRIC
CO., LTD.

APPROVED	RI. TAKAYASU	20170331
CHECKED	KI. NAGANUMA	20170331
DESIGNED	SG. CHAMURA	20170331
DRAWN	SG. CHAMURA	20170331

DRAWING NO. EDC-129430-01-00
PART NO. IX61G-A-10P(01)
CODE NO. CL251-0021-0-01 5 1/3

FORM HC0011-5-7

2019/12/24 12:59:25(JST) KH.OGAWA

RoHS2(10 substances conformity)
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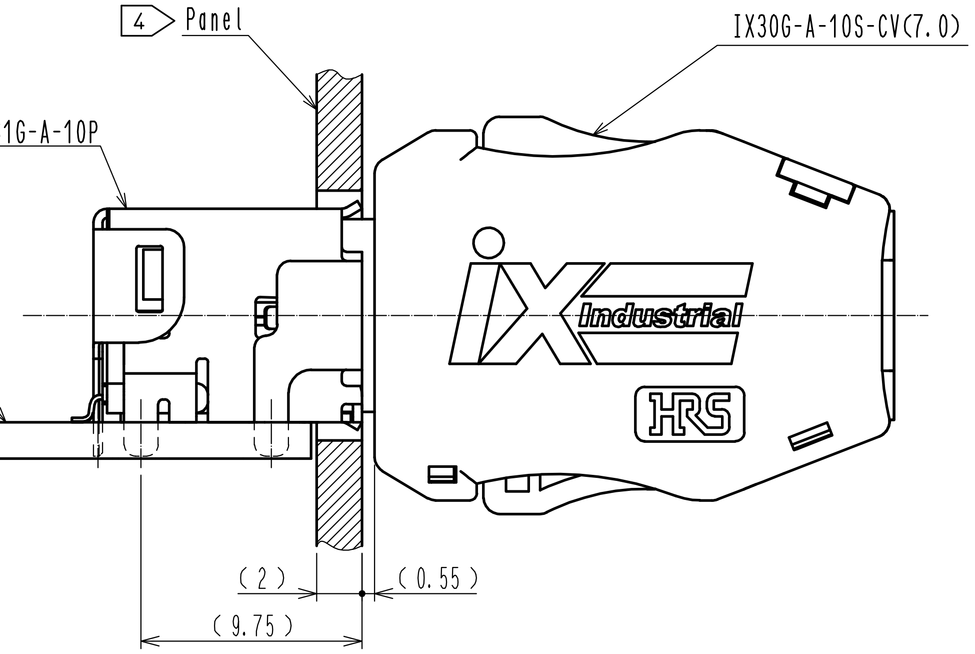
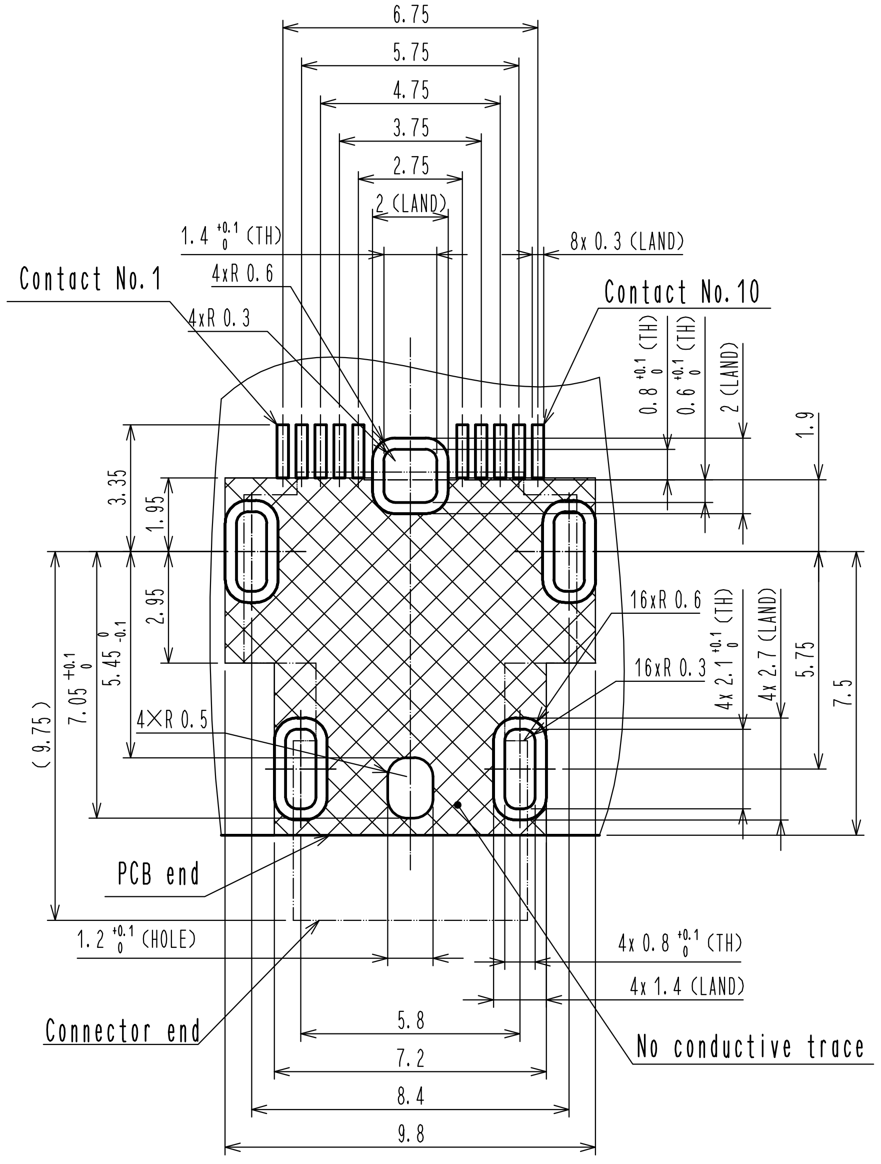
Mated Condition (Free)

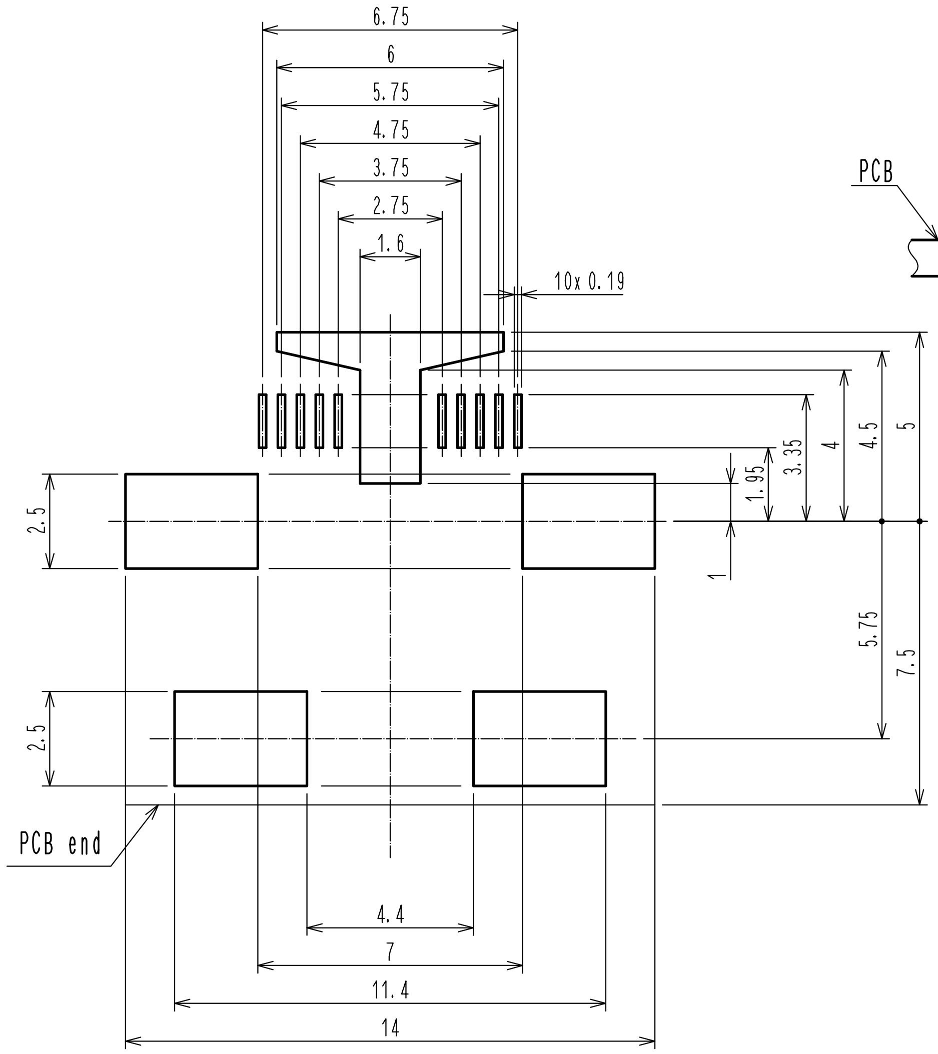


Reference PCB Layout (Connector Mounting Side) (t = 1.6)



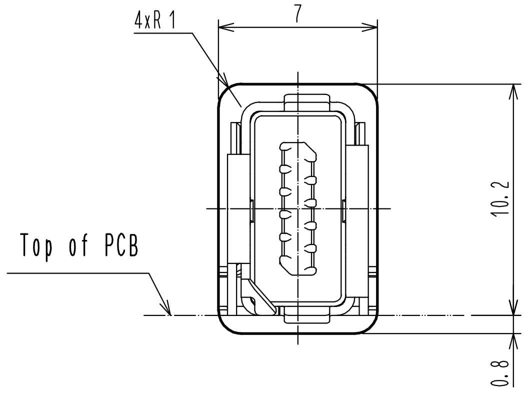
General tolerance is +/- 0.05

6 Reference Metal Mask Layout (t = 0.15)



General tolerance is +/- 0.02

4 Reference Dimensions of Panel Cutout (Free)



Dimension is reference.

6 Thickness of metal mask is 0.1 mm min.
Metal mask dimensions of the drawings described, are reference dimensions for 0.15 mm thickness metal mask.
Change the metal mask dimensions by thickness of the metal mask, thickness of PCB, component of solder paste and mounting conditions.
Change the metal mask dimensions in case of mounting IX61G-*-10P in parallel.
Change the metal mask dimensions, if there are other mounting parts or implementation pattern around the portion of mounting position of IX61G-*-10P.
Refer to the technical specification (ETAD-E3170-00) for different variations of the metal mask pattern width.

HRS	DRAWING NO.	EDC-129430-01-00
	PART NO.	IX61G-A-10P(01)
	CODE NO.	CL251-0021-0-01 5 2/3

RoHS2(10 substances conformity)
参考図:ご確認用。正式には別途納入仕様書をご請求願います。
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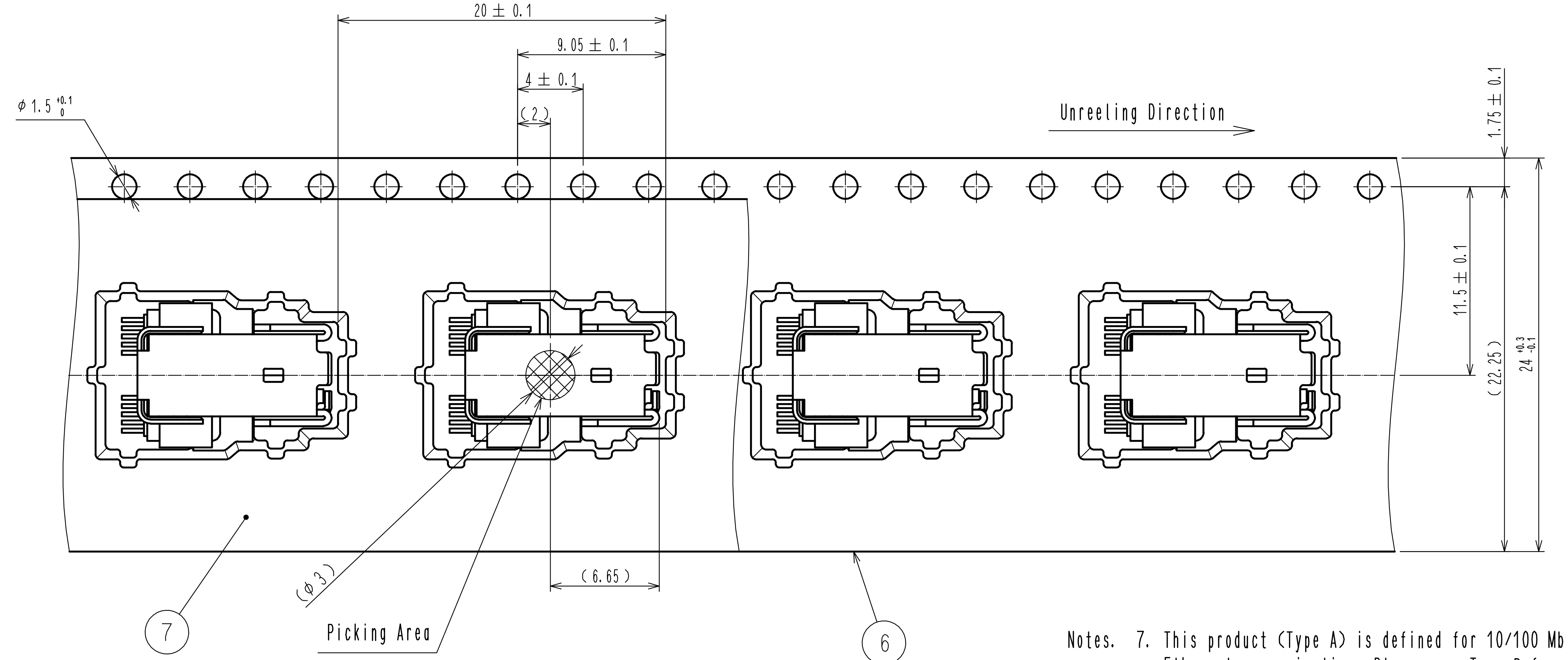
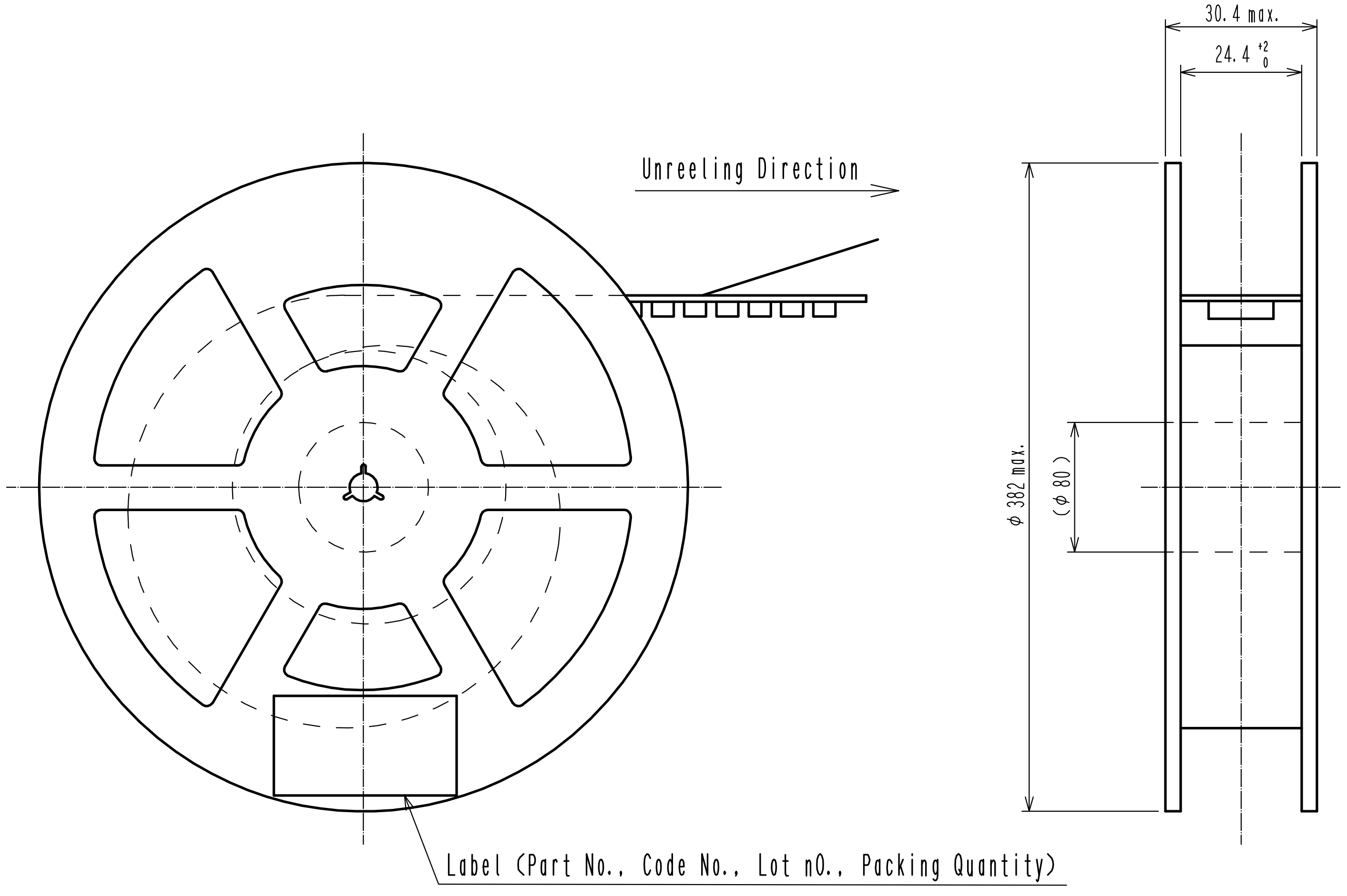
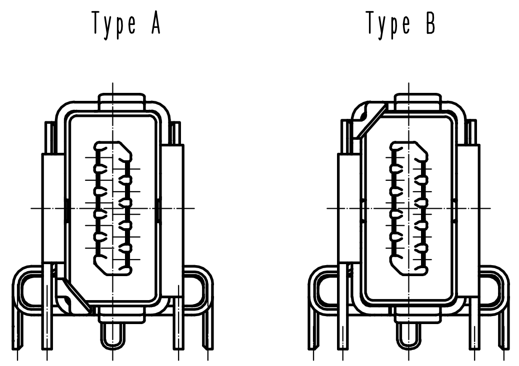
△5 3▷ Drawing for packing (Free)



Notes. 7. This product (Type A) is defined for 10/100 Mbit/s and 1/10 Gbit/s Ethernet communication. Please use Type B for all other non Ethernet applications like signaling, serial or other industrial bus communication systems.



Mating Shape


Type A
Type B

Pin Assignment For 10/100 Mbit/s And 1/10 Gbit/s Ethernet

Contact No.	Signal	
	10/100 Mbit/s	1/10 Gbit/s
1	TX+	BI_DA+
2	TX-	BI_DA-
3	N.C	GND
4	N.C	BI_DC+
5	N.C	BI_DC-
6	RX+	BI_DB+
7	RX-	BI_DB-
8	N.C	GND
9	N.C	BI_DD+
10	N.C	BI_DD-

HRS
DRAWING NO. EDC-129430-01-00
PART NO. IX61G-A-10P(01)
CODE NO. CL251-0021-0-01 △5 3/3

RoHS2(10 substances conformity)
参考図：ご確認用。正式には別途納入仕様書をご請求願います。
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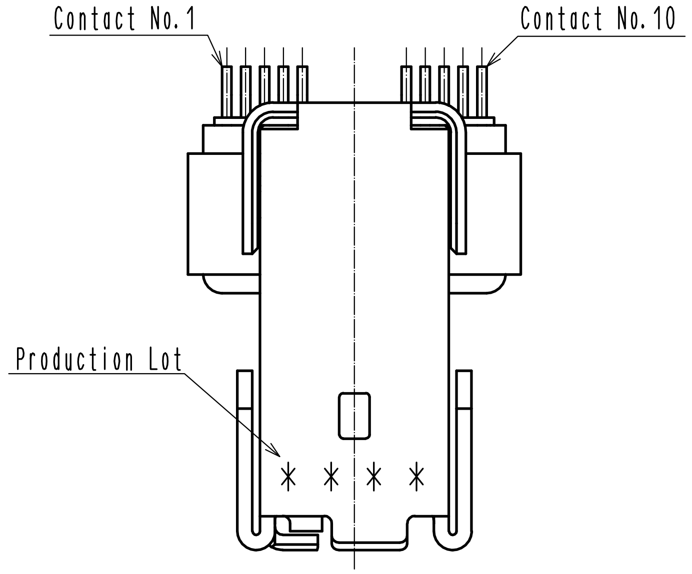
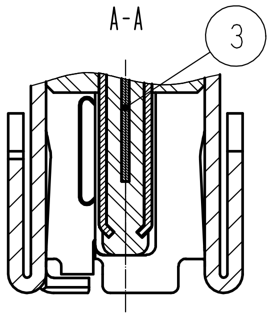




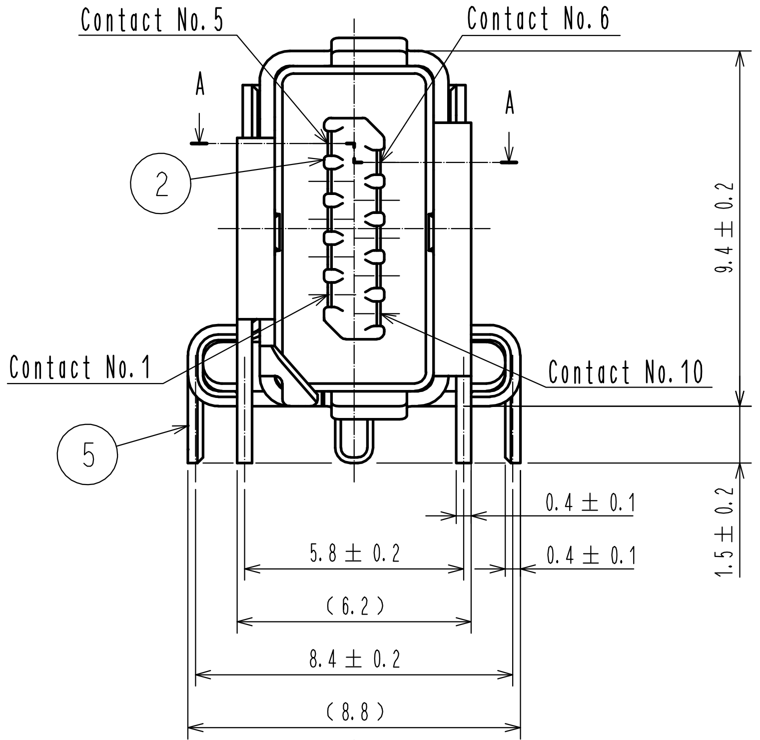
Notes. 1 Co-planarity is within 0.1 mm.

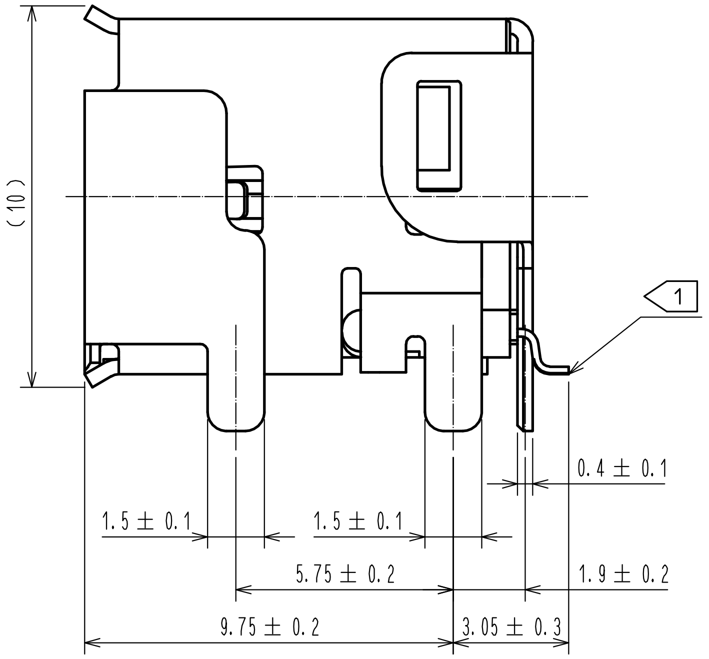
2. As for part No.5 the performance remains good even if there are rubbing wounds by the assembly process.
And the perfomance remains good though there might be a difference inthe pating luster beteween each plating lots.

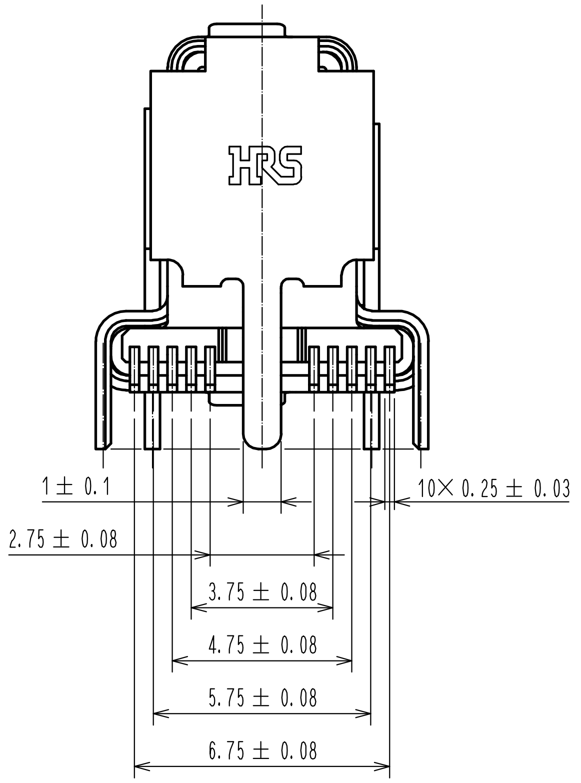
3 Per reel : 400 pcs.

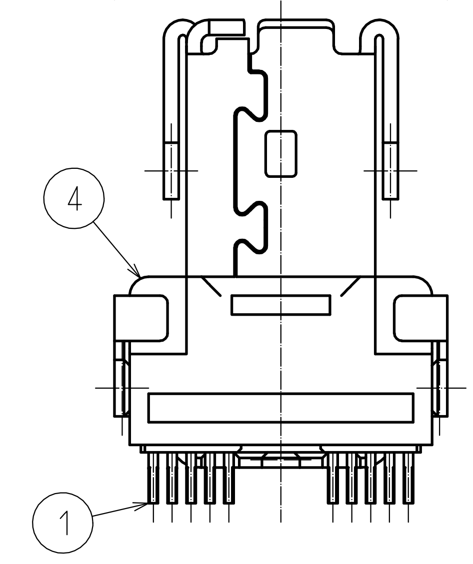
4 Refer to the mated condition diagram for the panel thickness and layout.

5. This produt is mounted by reflow soldering.
Refer to specification sheet ELC-129430-00-00 for reflow soldering.









NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
			7	PE	
3	Stainless Steel		6	PS	
2	LCP	Gray、UL94V-0	5	Stainless Steel	Surface : Tin 1 μm min. Under plating : Nickel 0.2 μm min.
1	Copper Alloy	Contact area : Gold 0.2 μm min. Lead area : Gold 0.03 μm min. Under plating : Nickel 2 μm min.	4	LCP	Gray、UL94V-0

UNITS		SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm		5 : 1	4	1	DIS-E-00002758	MT. YASUDA	KI. NAGANUMA	20191219

HRS HIROSE ELECTRIC CO., LTD.

APPROVED	:RI. TAKAYASU	20170328	DRAWING NO.	EDC-129430-00-00
CHECKED	:KI. NAGANUMA	20170327	PART NO.	IX61G-A-10P
DESIGNED	:TS. SAKAIZAWA	20170327	CODE NO.	CL251-0021-0-00 4 1/3
DRAWN	:TS. SAKAIZAWA	20170327		

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RoHS2(10 substances conformity)
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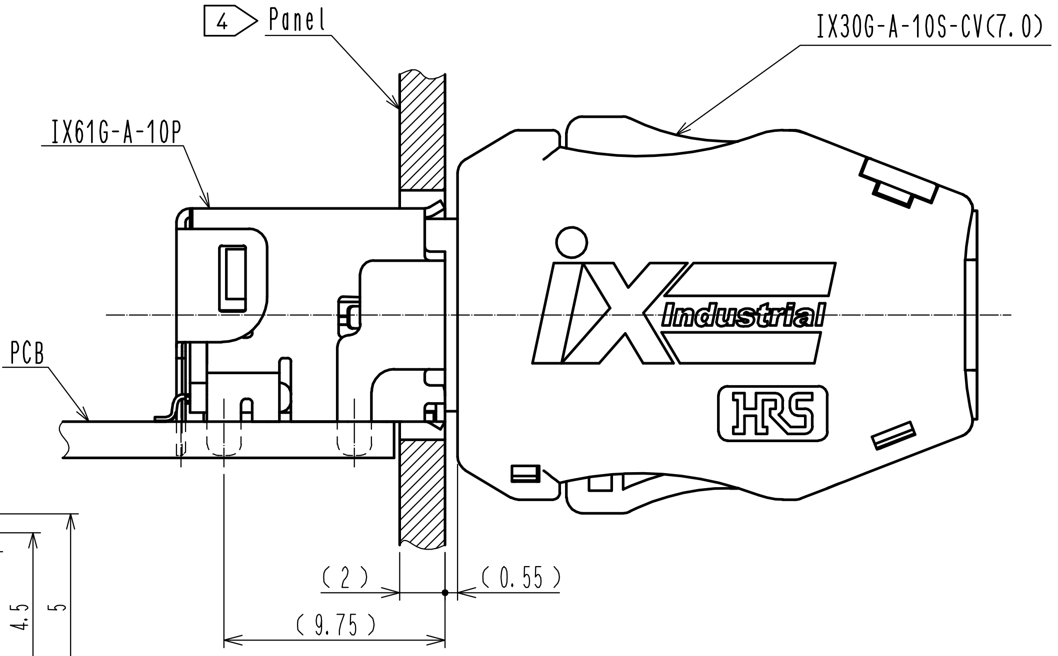
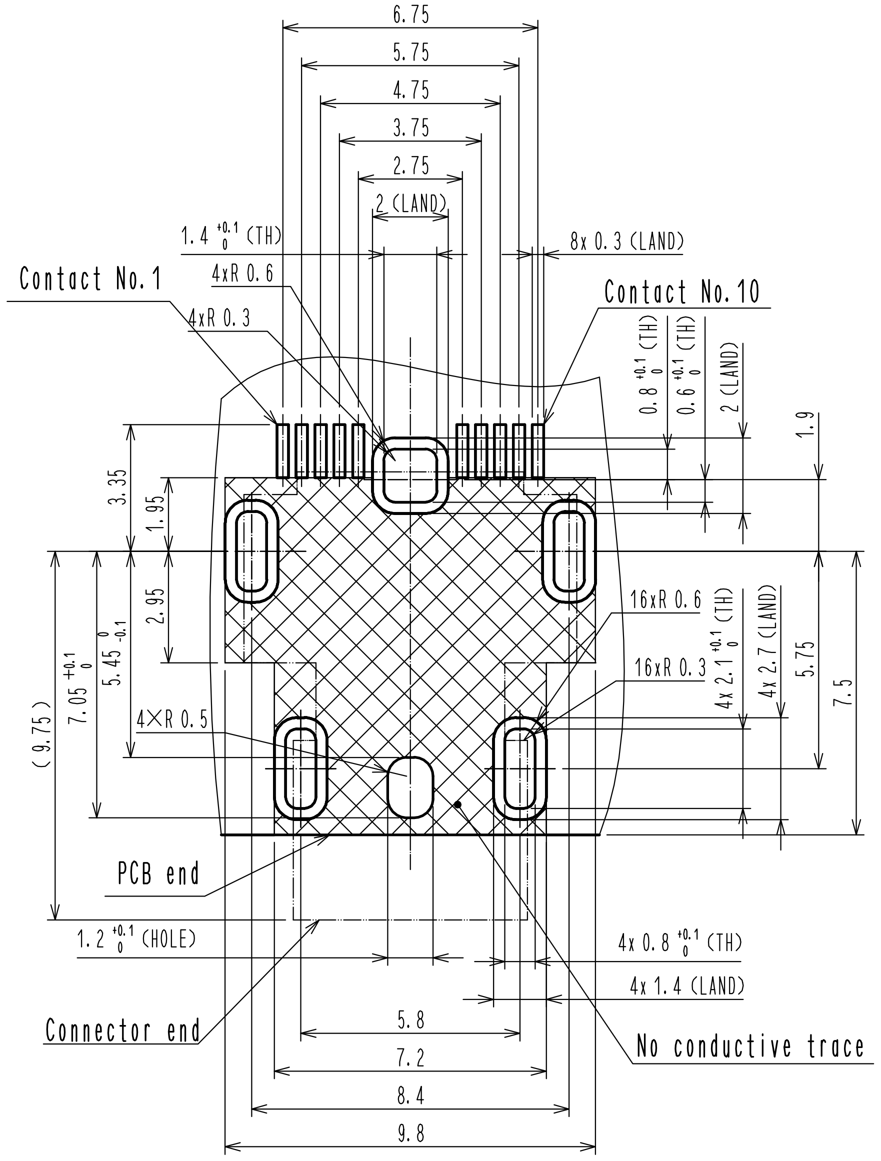
Mated Condition (Free)

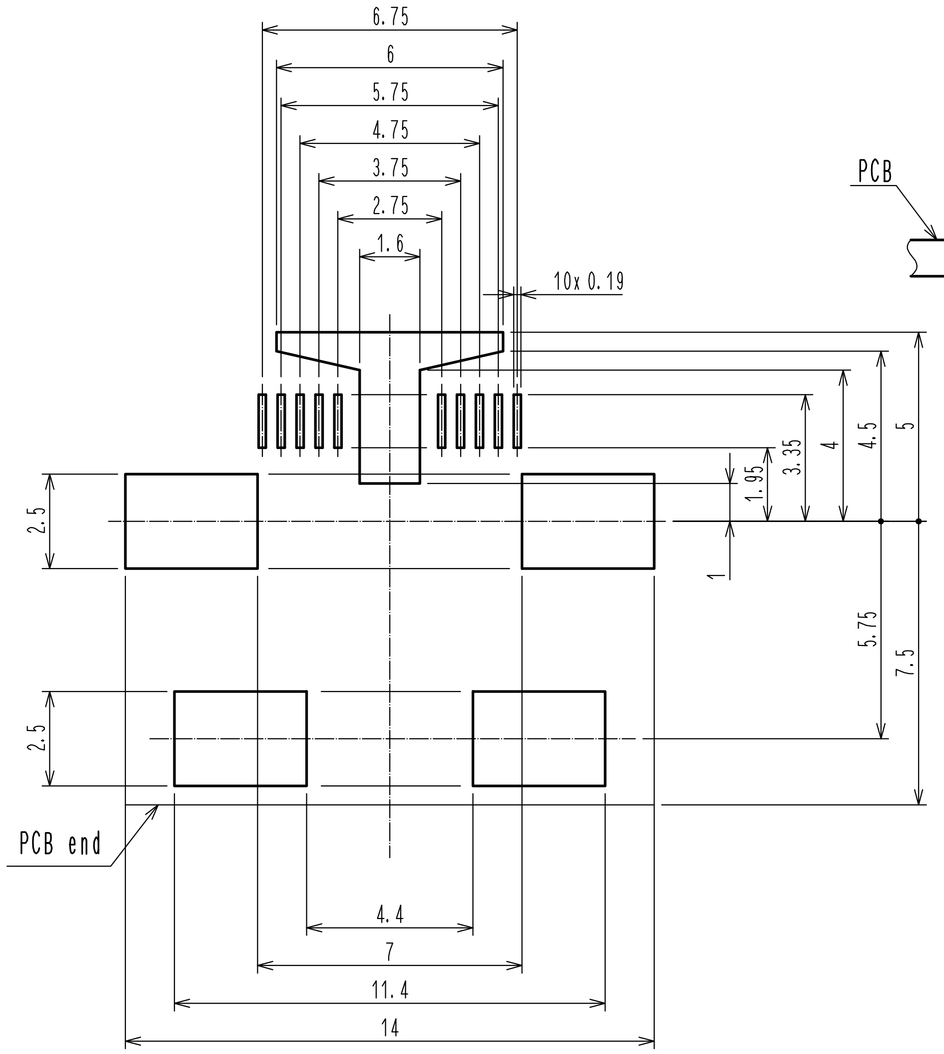


Reference PCB Layout (Connector Mounting Side) (t = 1.6)



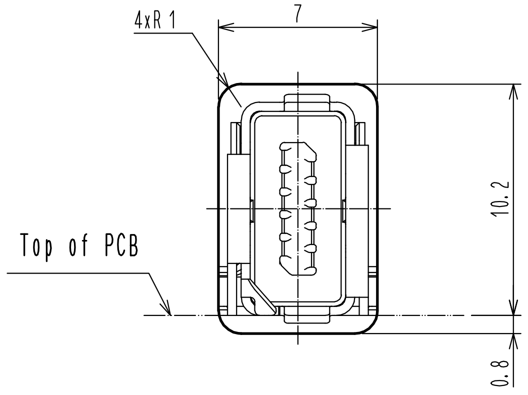
General tolerance is +/- 0.05

6 Reference Metal Mask Layout (t = 0.15)



General tolerance is +/- 0.02

4 Reference Dimensions of Panel Cutout (Free)



Dimension is reference.

6 Thickness of metal mask is 0.1 mm min.
Metal mask dimensions of the drawings described, are reference dimensions for 0.15 mm thickness metal mask.
Change the metal mask dimensions by thickness of the metal mask, thickness of PCB, component of solder paste and mounting conditions.
Change the metal mask dimensions in case of mounting IX61G-*-10P in parallel.
Change the metal mask dimensions, if there are other mounting parts or implementation pattern around the portion of mounting position of IX61G-*-10P.
Refer to the technical specification (ETAD-E3170-00) for different variations of the metal mask pattern width.

HRS	DRAWING NO.	EDC-129430-00-00
	PART NO.	IX61G-A-10P
	CODE NO.	CL251-0021-0-00 4 2/3

2019/12/24 12:58:23(JST) KH.OGAWA

RoHS2(10 substances conformity)
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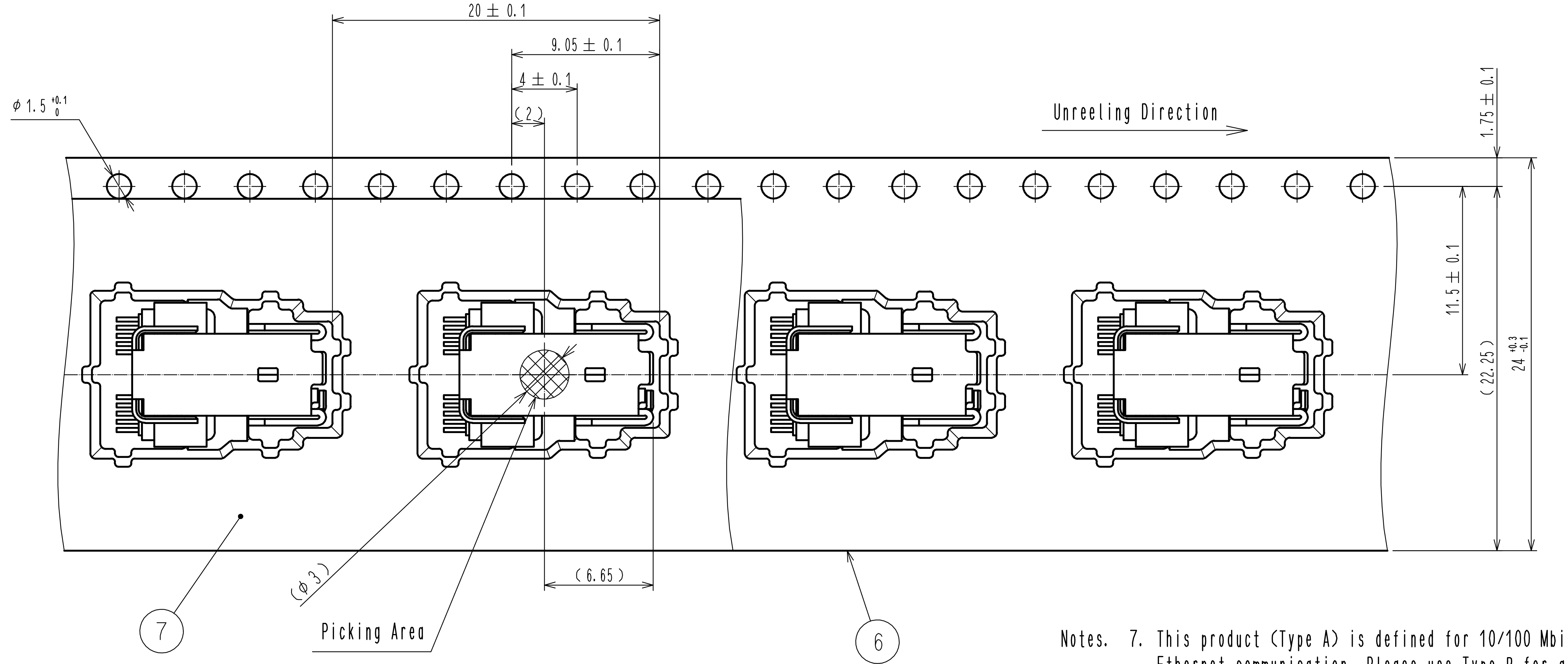
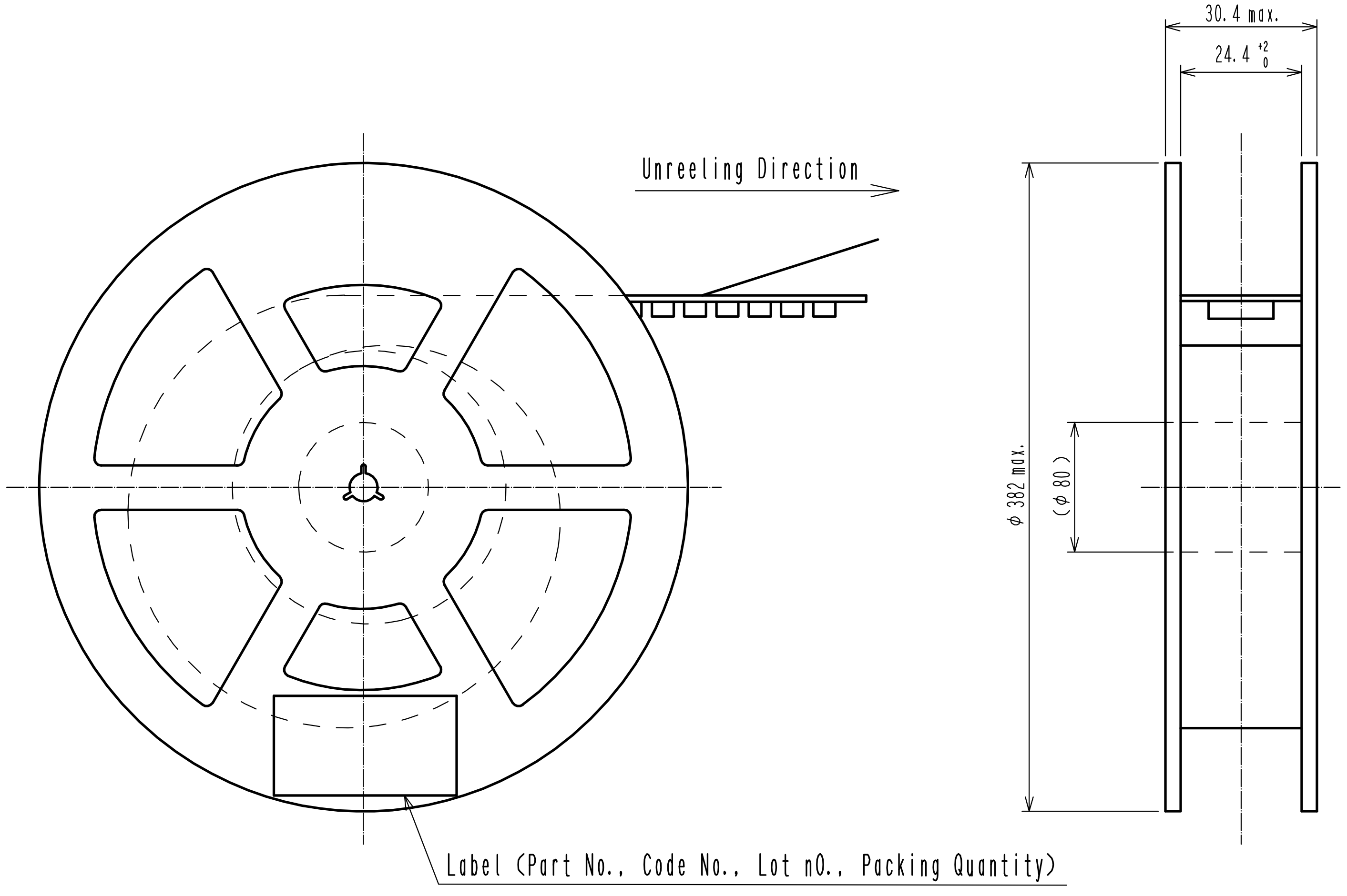
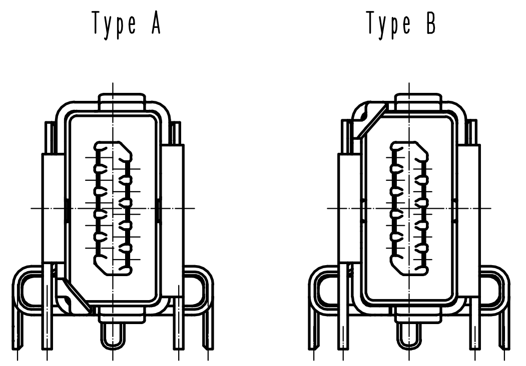
△4 3▷ Drawing for packing (Free)



Notes. 7. This product (Type A) is defined for 10/100 Mbit/s and 1/10 Gbit/s Ethernet communication. Please use Type B for all other non Ethernet applications like signaling, serial or other industrial bus communication systems.



Mating Shape

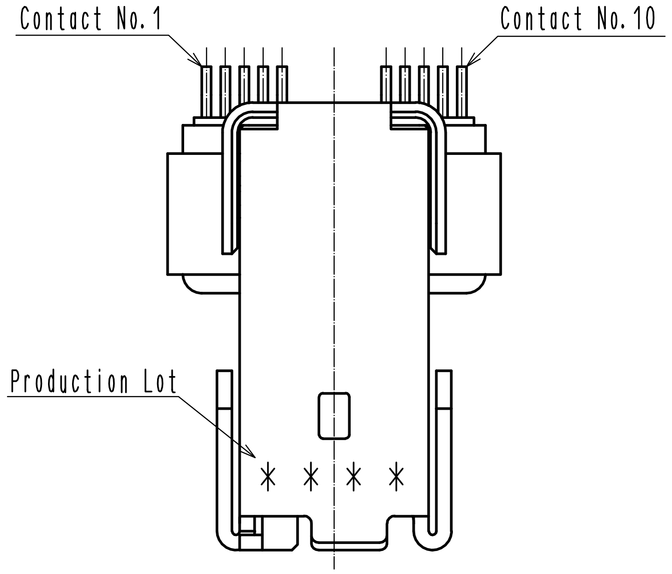


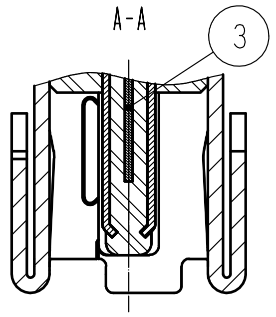
Pin Assignment For 10/100 Mbit/s And 1/10 Gbit/s Ethernet

Contact No.	Signal	
	10/100 Mbit/s	1/10 Gbit/s
1	TX+	BI_DA+
2	TX-	BI_DA-
3	N.C	GND
4	N.C	BI_DC+
5	N.C	BI_DC-
6	RX+	BI_DB+
7	RX-	BI_DB-
8	N.C	GND
9	N.C	BI_DD+
10	N.C	BI_DD-

DRAWING NO.	EDC-129430-00-00
PART NO.	IX61G-A-10P
CODE NO.	CL251-0021-0-00 △4 3/3

2019/12/24 13:01:21(JST) KH.OGAWA





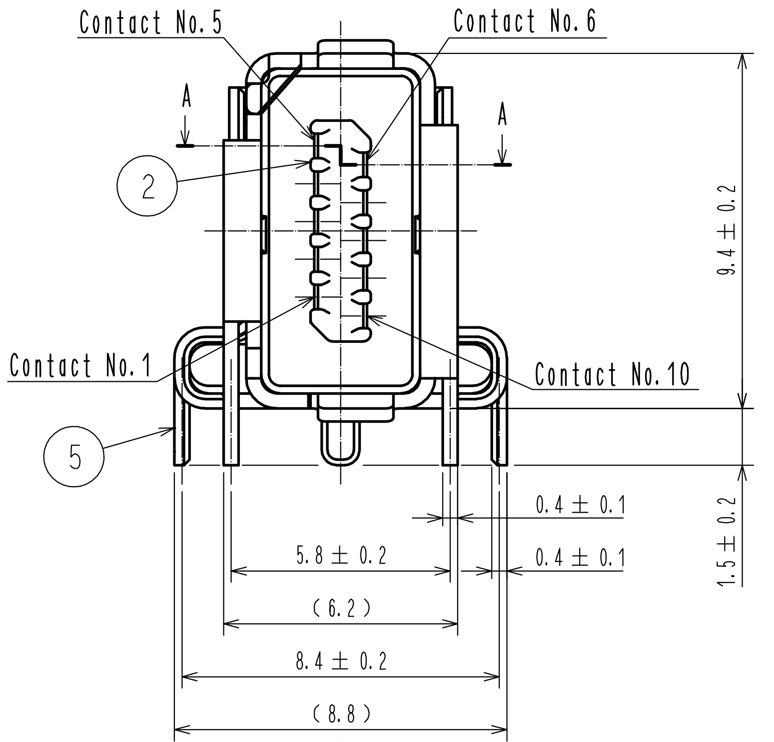
Notes. 1 Co-planarity is within 0.1 mm.

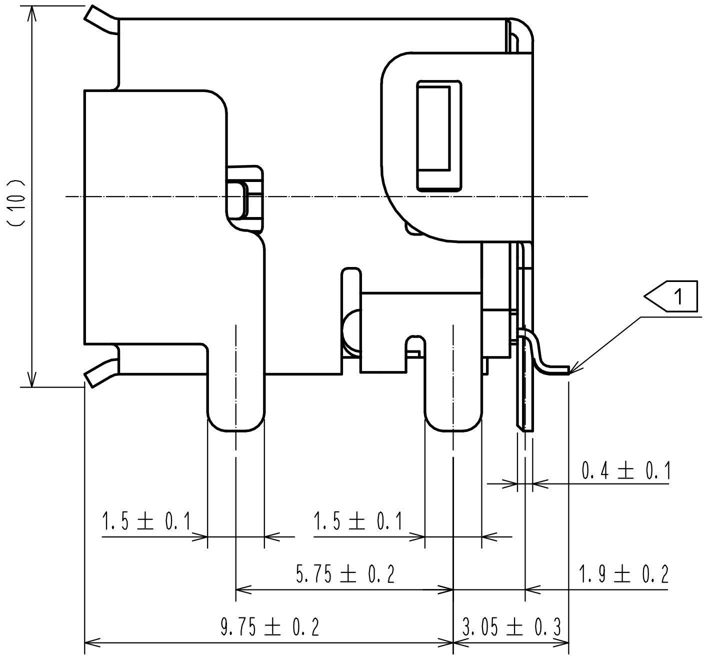
2. As for part No.5 the performance remains good even if there are rubbing wounds by the assembly process. And the perfomance remains good though there might be a difference inthe pating luster betewen each plating lots.

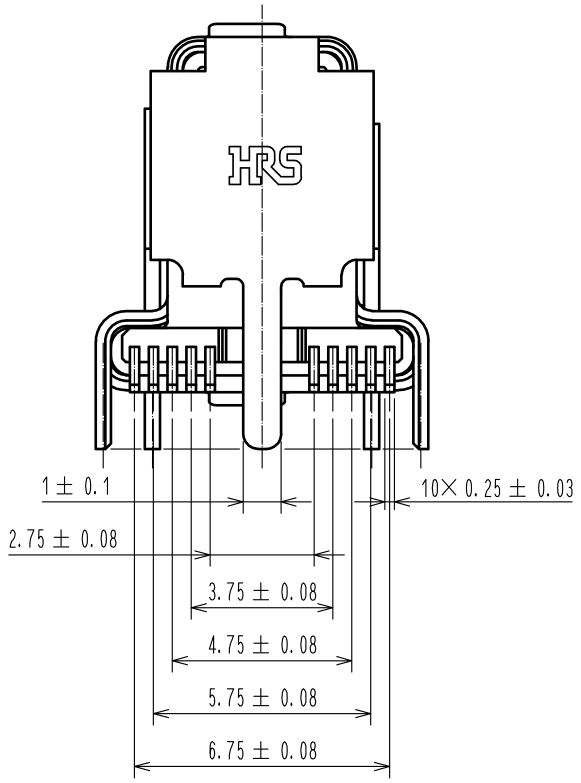
3 Per reel : 400 pcs.

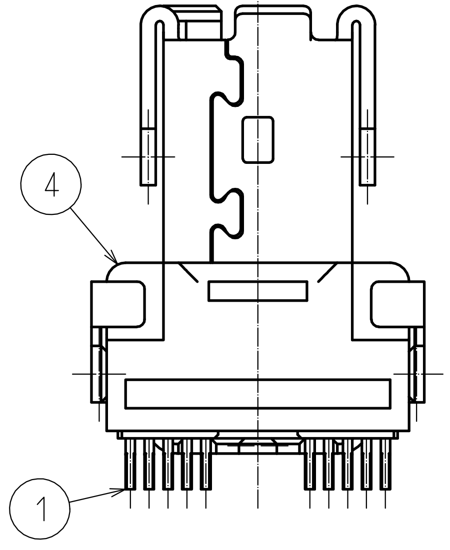
4 Refer to the mated condition diagram for the panel thickness and layout.

5. This produt is mounted by reflow soldering. Refer to specification sheet ELC-129488-01-00 for reflow soldering.









3	Stainless Steel		7	PE	
2	LCP	Gray、UL94V-0	6	PS	
1	Copper Alloy	Contact area : Palladium-Nickel 0.75 μm min. + Gold 0.05 μm min. Wiring area : Gold 0.03 μm min. Under plating : Nickel 2 μm min.	5	Stainless Steel	Surface : Tin 1 μm min. Under plating : Nickel 0.2 μm min.
			4	LCP	Gray、UL94V-0
	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

UNITS		SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	⊕	5 : 1	4	1	DIS-E-00002758	MT. YASUDA	KI. NAGANUMA	20191219

HIROSE ELECTRIC CO., LTD.

APPROVED	RI. TAKAYASU	20170331
CHECKED	KI. NAGANUMA	20170331
DESIGNED	SG. CHAMURA	20170331
DRAWN	SG. CHAMURA	20170331

DRAWING NO. EDC-129488-01-00
PART NO. IX61G-B-10P(01)
CODE NO. CL251-0026-0-01 4 1/3

FORM HC0011-5-7

RoHS2(10 substances conformity)
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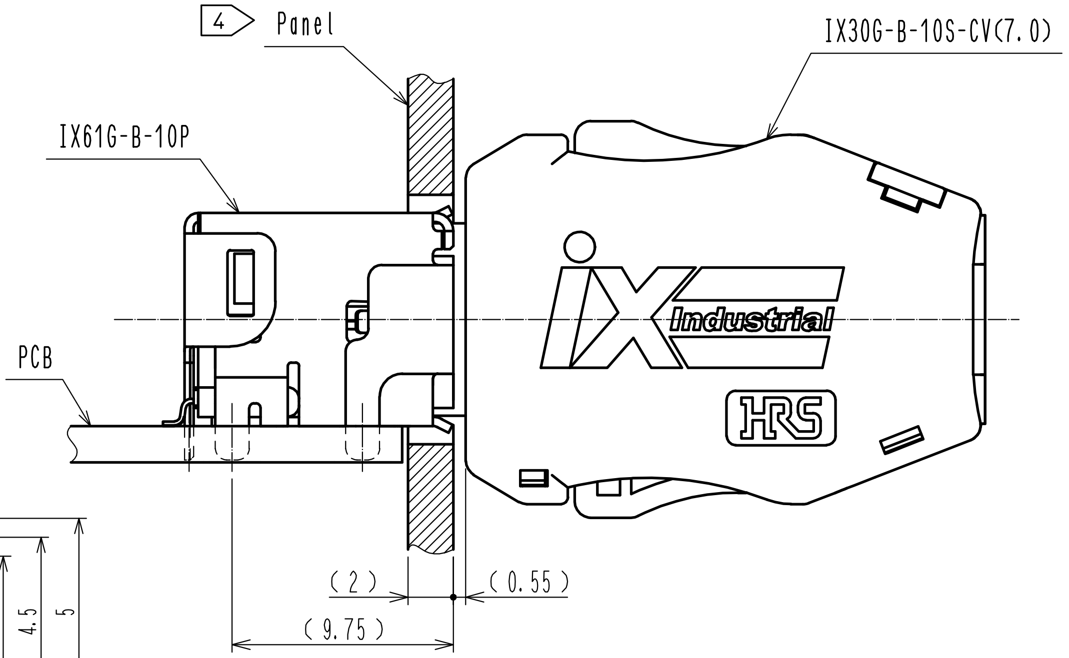
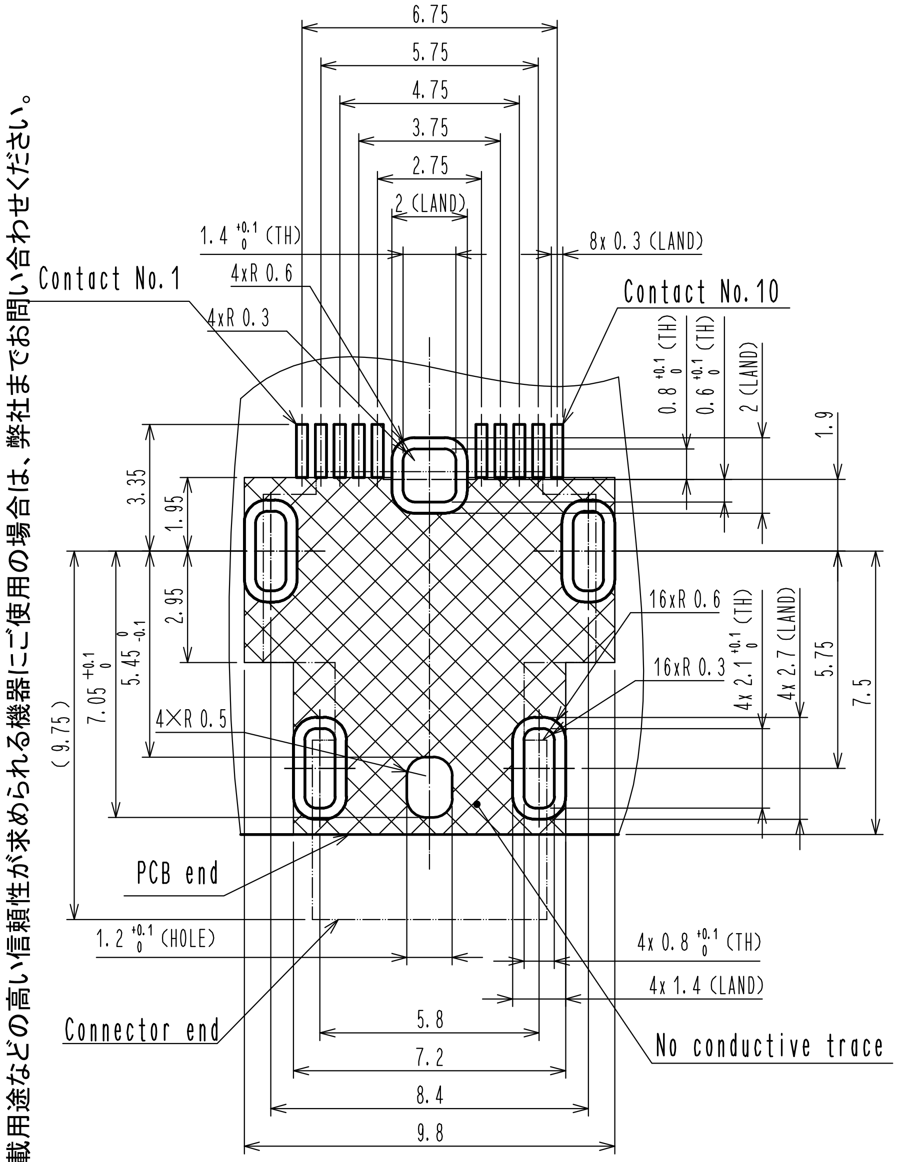
Mated Condition (Free)

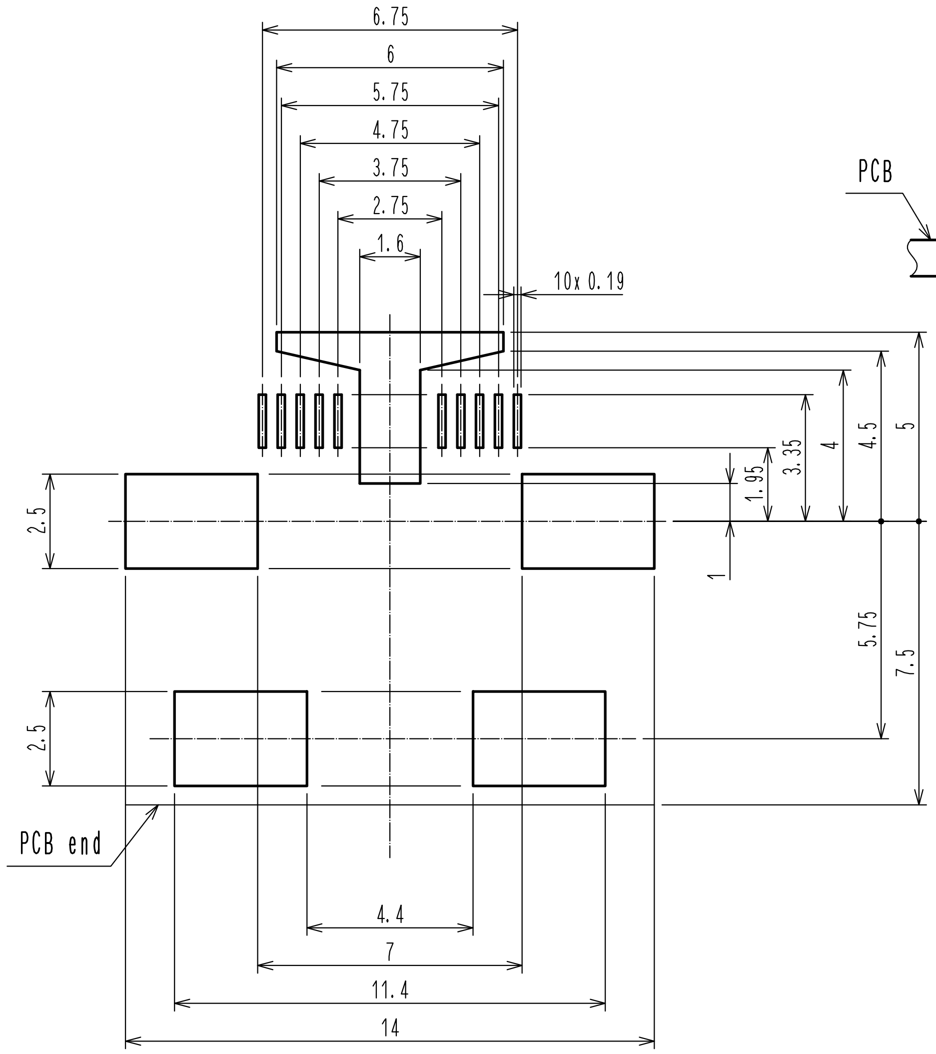


Reference PCB Layout (Connector Mounting Side) (t = 1.6)



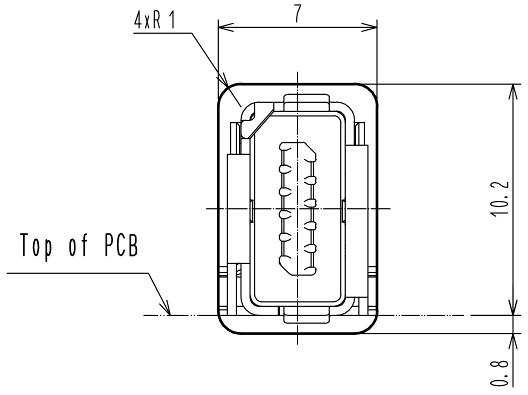
General tolerance is +/- 0.05

6 Reference Metal Mask Layout (t = 0.15)



General tolerance is +/- 0.02

4 Reference Dimensions of Panel Cutout (FREE)



Dimension is reference.

6 Thickness of metal mask is 0.1 mm min.
Metal mask dimensions of the drawings described, are reference dimensions for 0.15 mm thickness metal mask.
Change the metal mask dimensions by thickness of the metal mask, thickness of PCB, component of solder paste and mounting conditions.
Change the metal mask dimensions in case of mounting IX61G-*-10P in parallel.
Change the metal mask dimensions, if there are other mounting parts or implementation pattern around the portion of mounting position of IX61G-*-10P.
Refer to the technical specification (ETAD-E3170-00) for different variations of the metal mask pattern width.

HRS	DRAWING NO.	EDC-129488-01-00
	PART NO.	IX61G-B-10P(01)
	CODE NO.	CL251-0026-0-01 ⚠4 2/3

2019/12/24 13:01:21(JST) KH.OGAWA

RoHS2(10 substances conformity)
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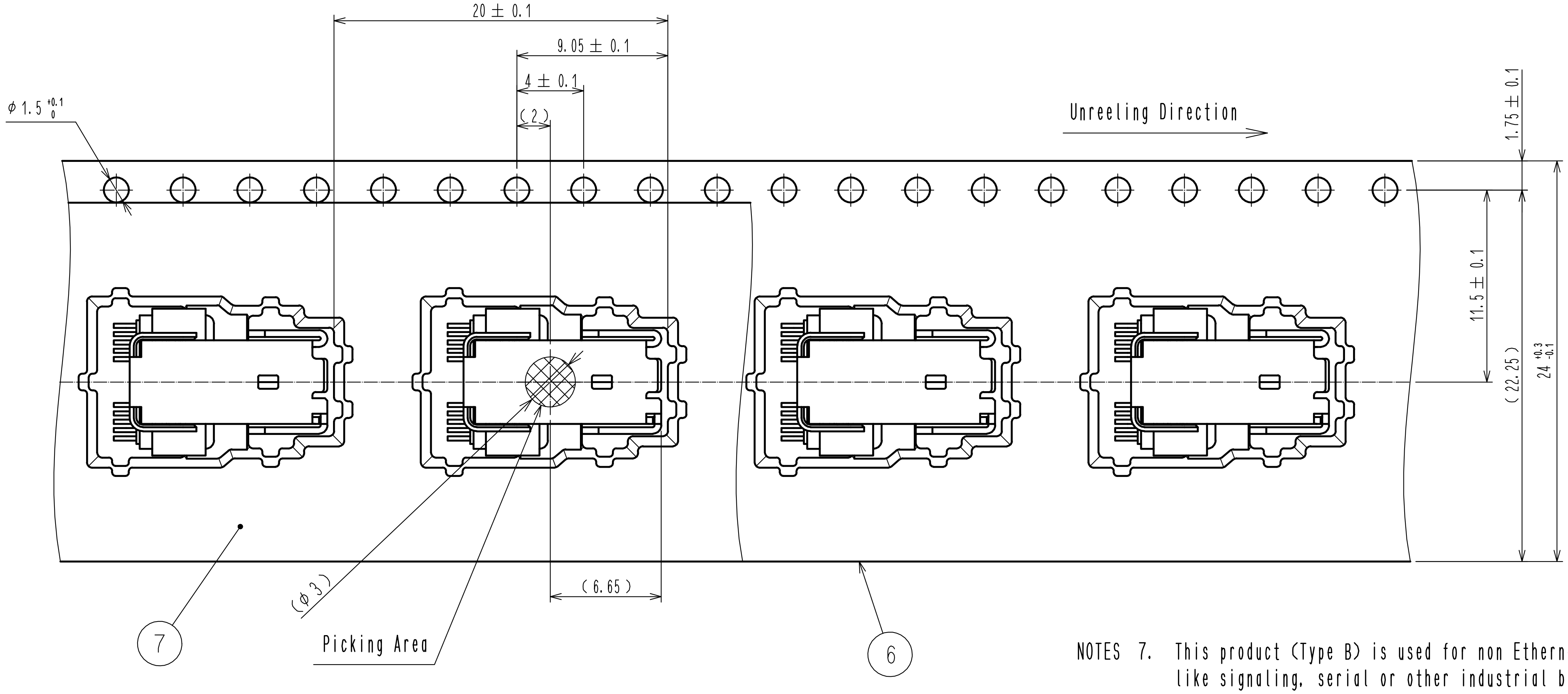
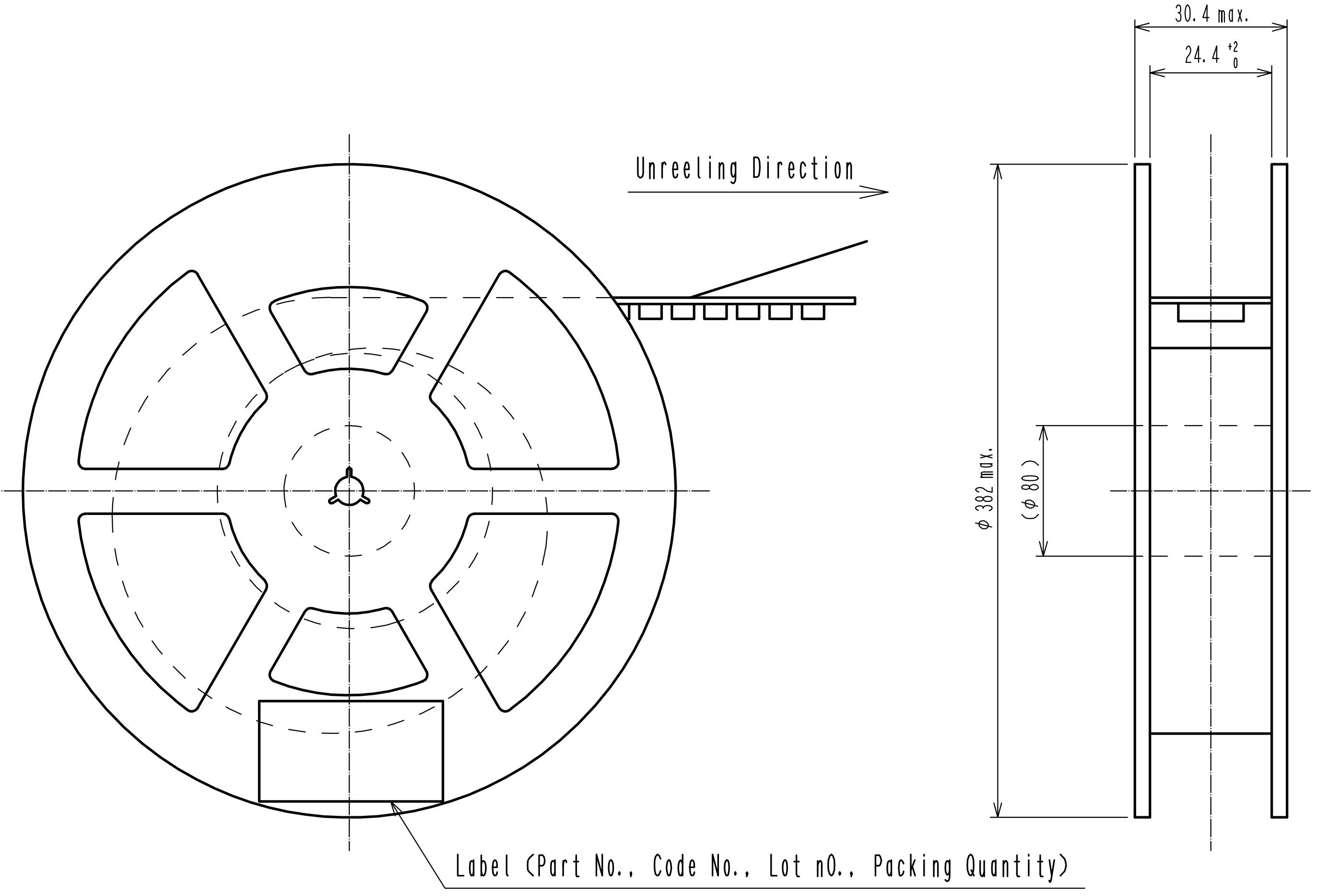
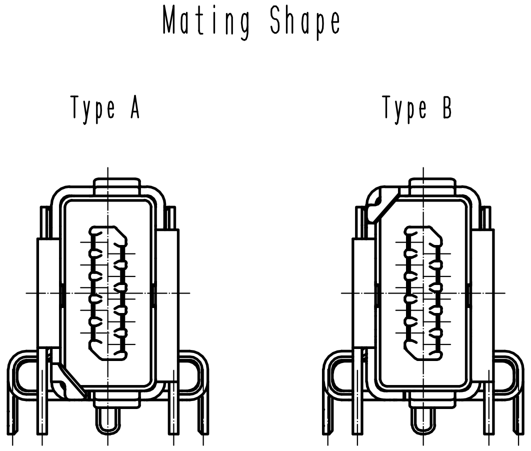
⚠4 3 Drawing for packing (Free)



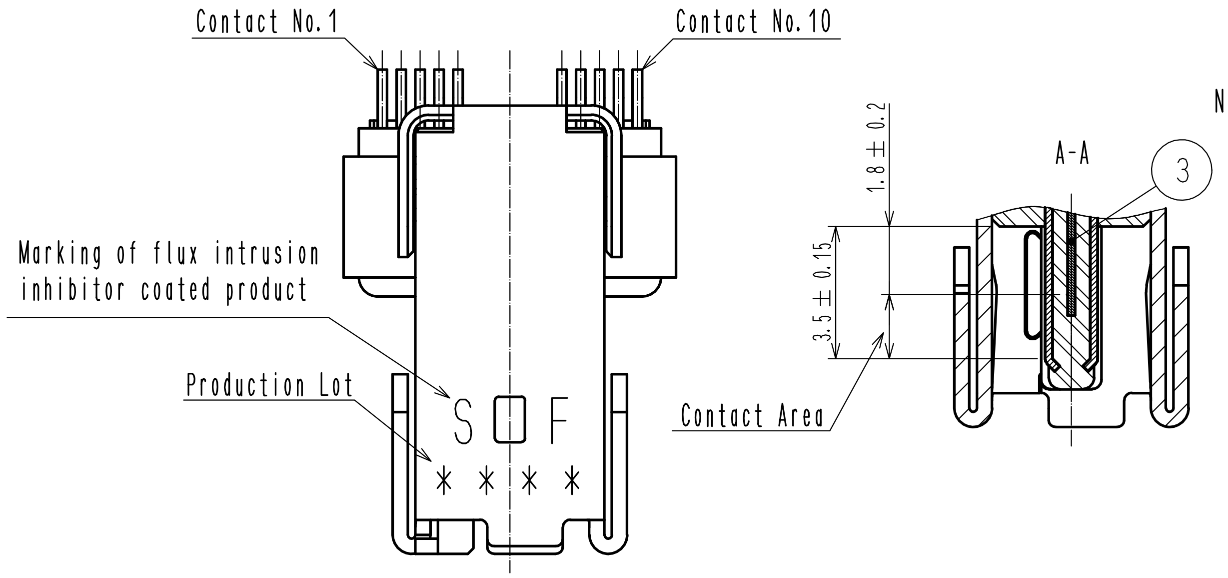
NOTES 7. This product (Type B) is used for non Ethernet applications
like signaling, serial or other industrial bus communication systems.
Please use Type A for 10/100Mbit/s and 1/10 Gbit/s Ethernet communication.





HRS	DRAWING NO.	EDC-129488-01-00
	PART NO.	IX61G-B-10P(01)
	CODE NO.	CL251-0026-0-01 ⚠4 3/3

FORM HC0011-5-8



Notes.
1 Co-planarity is within 0.1 mm.

2. As for part No.5 the performance remains good even if there are rubbing wounds by the assembly process.
And the perfomance remains good though there might be a difference inthe pating luster betewen each plating lots.

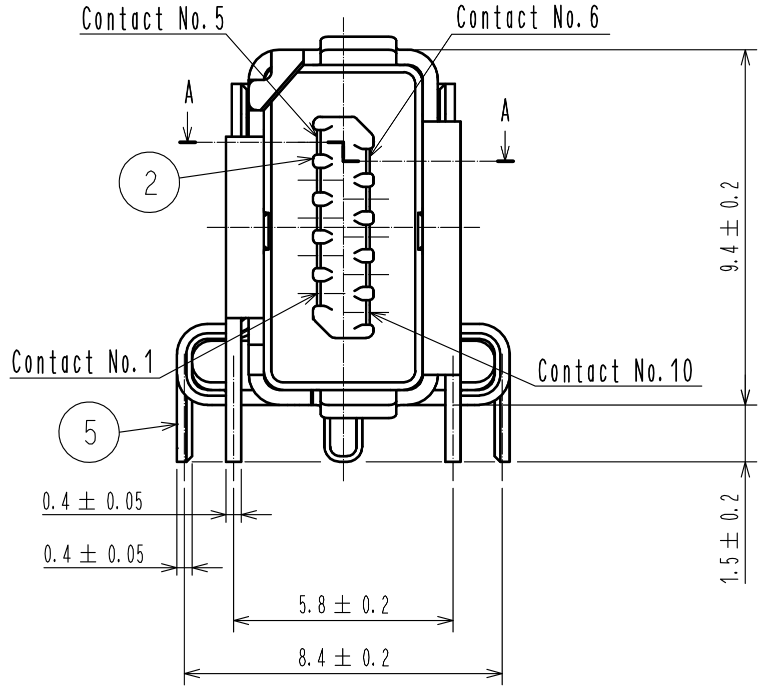
3 Per reel : 250 pcs.

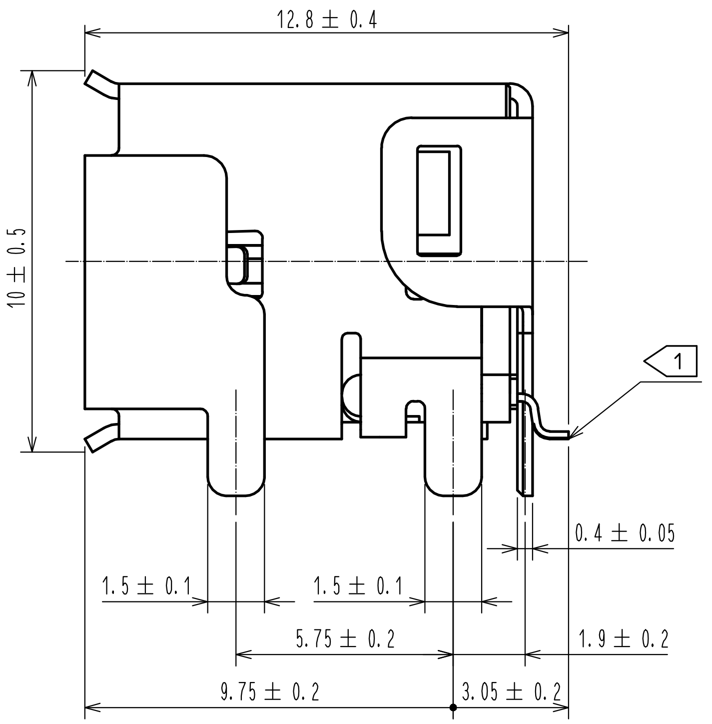
4 Refer to the mated condition diagram for the panel thickness and layout.

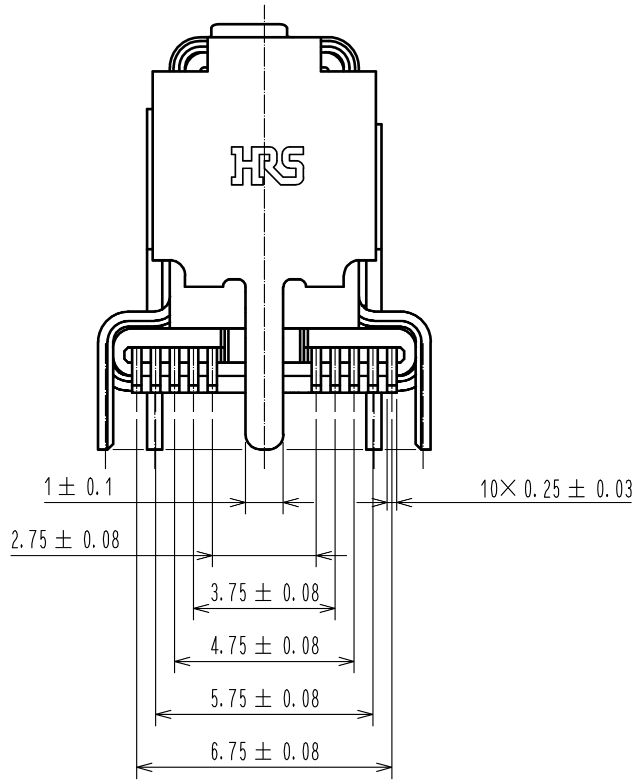
5. This produt is mounted by reflow soldering.
Refer to specification sheet ELC-129488-02-01 for reflow soldering.

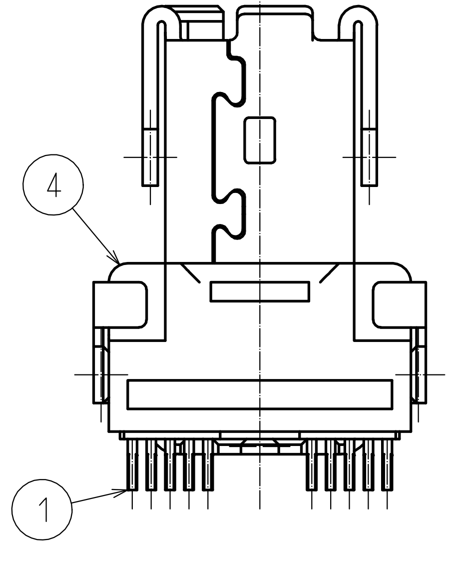
6. MSL1 equivalent, however floor life is one year after delivery

7. Emboss tape, cover tape and plastic reel are composed of antistatic material









3	Stainless Steel		7	PE	
2	LCP	Gray、UL94V-0	6	PS	
1	Copper Alloy	Contact area : Palladium-Nickel 0.75 μm min. + Gold 0.05 μm min. Wiring area : Gold 0.03 μm min. Under plating : Nickel 2 μm min.	5	Stainless Steel	Surface : Tin 1 μm min. Under plating : Nickel 0.2 μm min. Flux intrusion inhibitor
			4	LCP	Gray、UL94V-0
	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

UNITS		SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm		2 : 1	3	1	DIS-E-00002758	MT. YASUDA	KI. NAGANUMA	20191219

HIROSE ELECTRIC CO., LTD.

APPROVED	RI. TAKAYASU	20180405	DRAWING NO. EDC-129488-02-00
CHECKED	KI. NAGANUMA	20180405	PART NO. IX61G-B-10P(02)
DESIGNED	JY. IGA	20180405	CODE NO. CL251-0026-0-02 3 1/3
DRAWN	JY. IGA	20180405	

RoHS2(10 substances conformity)
参考図:ご確認用。正式には別途納入仕様書をご請求願います。
本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。

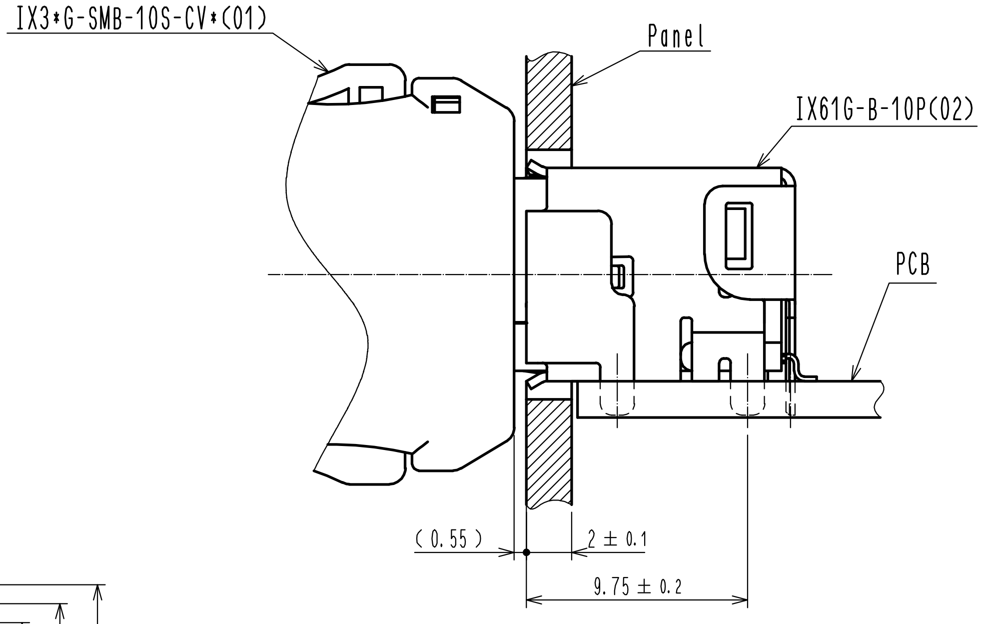
2019/12/24 12:51:32(JST) KH.OGAWA

RoHS2(10 substances conformity)

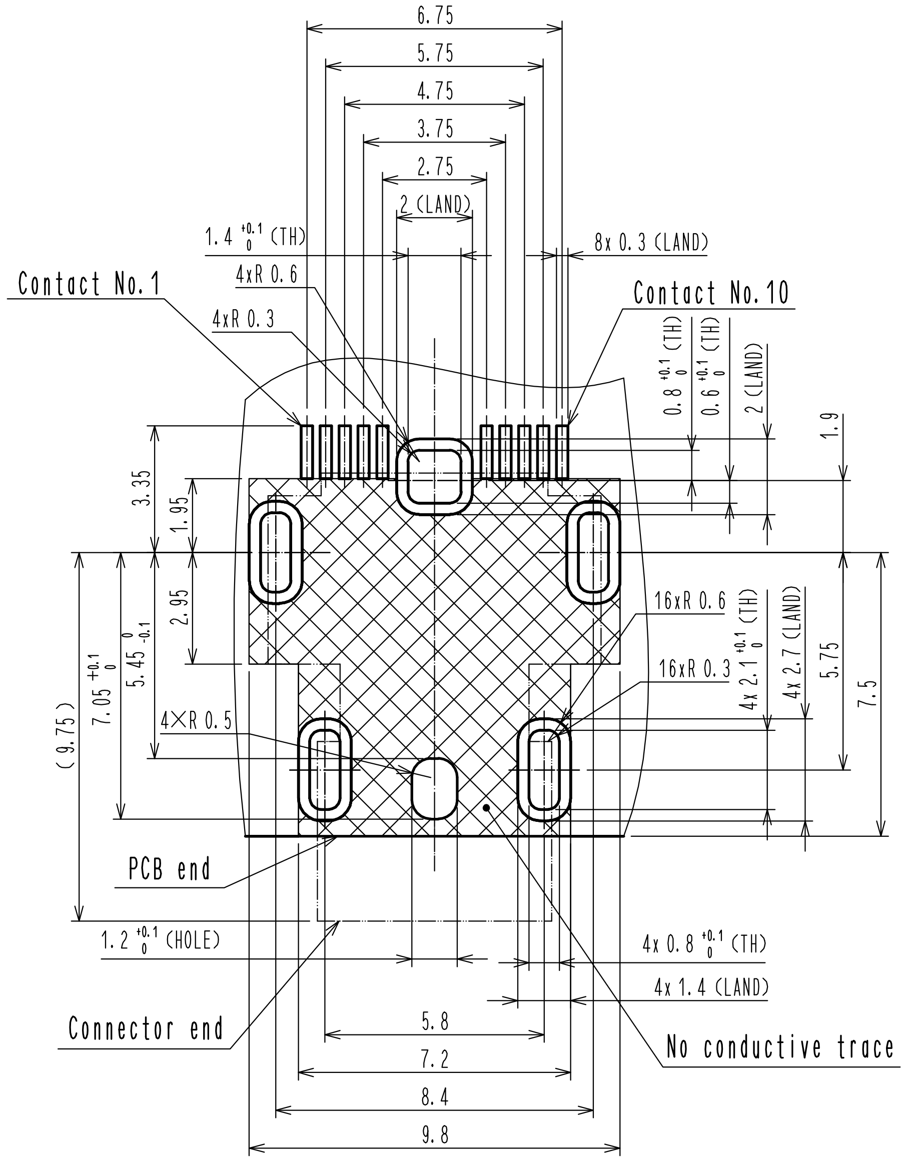
参考図・ご確認用。正式には別途納入仕様書をご請求願います。

本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。

4 Mated Condition (Free)

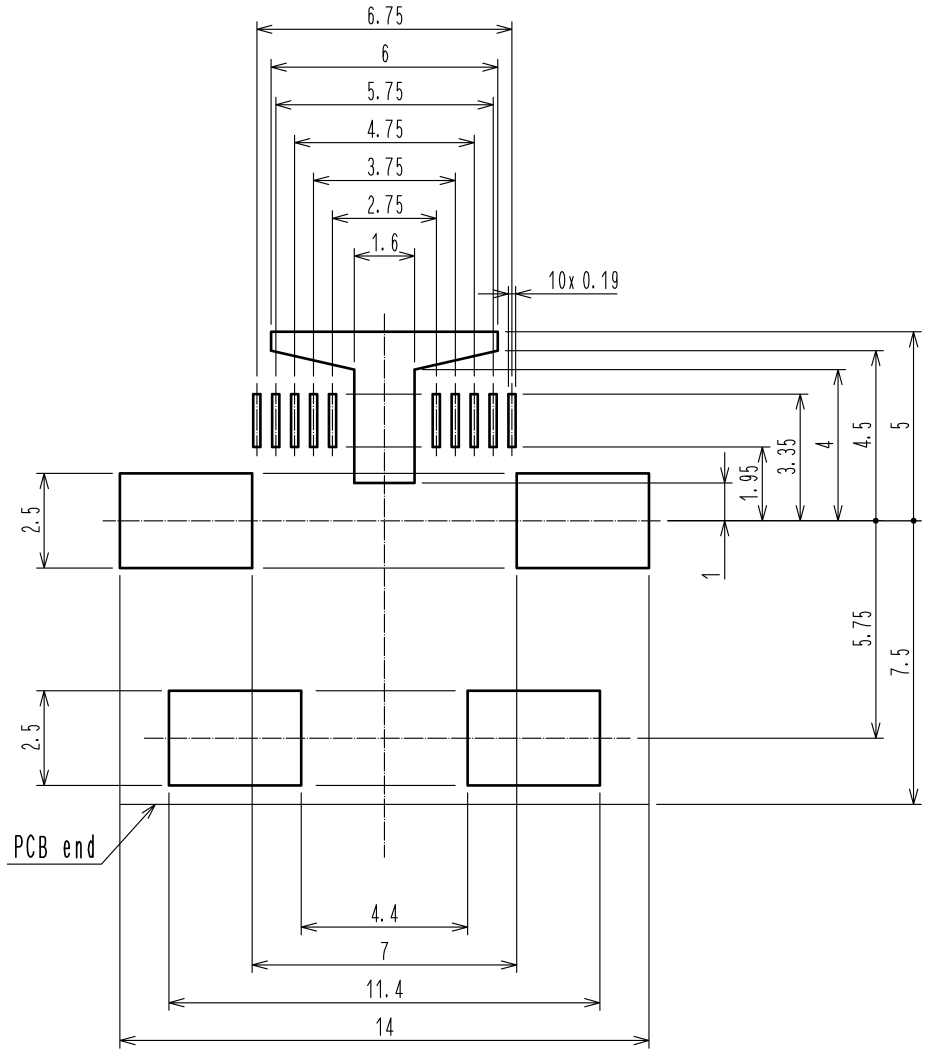


Reference PCB Layout (Connector Mounting Side) (t = 1.6)



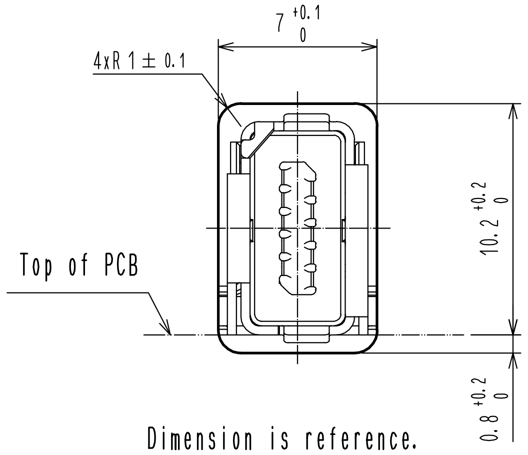
General tolerance is +/- 0.05

Reference Metal Mask Layout (t = 0.15)



General tolerance is +/- 0.02

4 Reference Dimensions of Panel Cutout (FREE)



Dimension is reference.

HRS

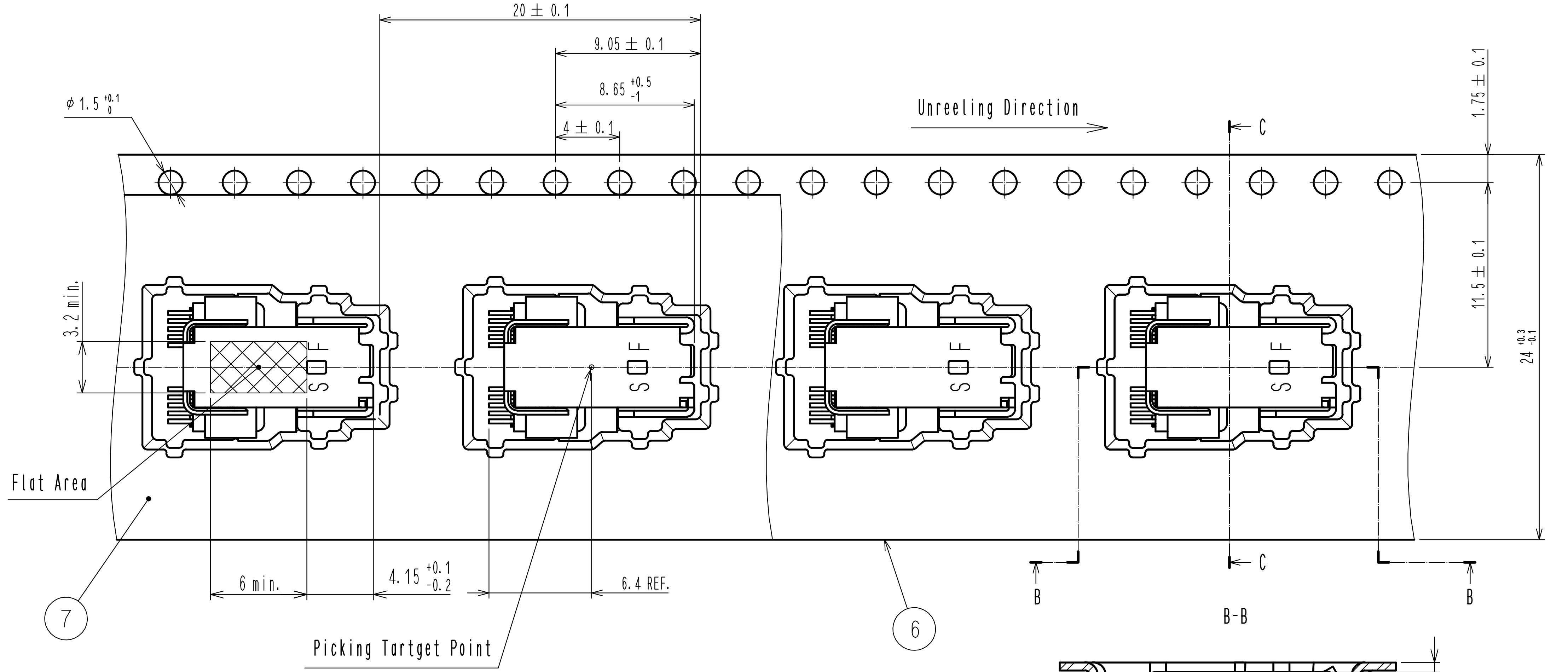
DRAWING NO.	EDC-129488-02-00	
PART NO.	IX61G-B-10P(02)	
CODE NO.	CL251-0026-0-02	3 2/3

FORM HC0011-5-8

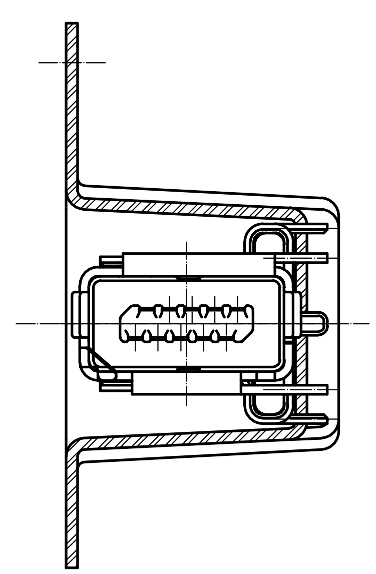
2019/12/24 12:51:32(JST) KH.OGAWA

RoHS2(10 substances conformity)
参考図：ご確認用。正式には別途納入仕様書をご請求願います。
本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。

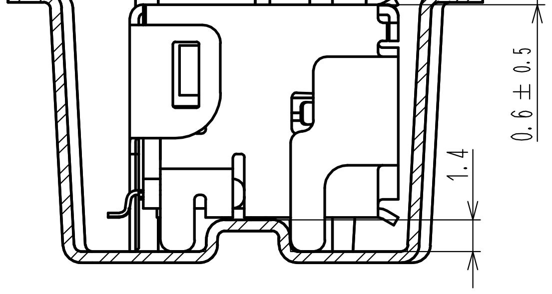
△3 ▷3 Drawing for packing (Free)

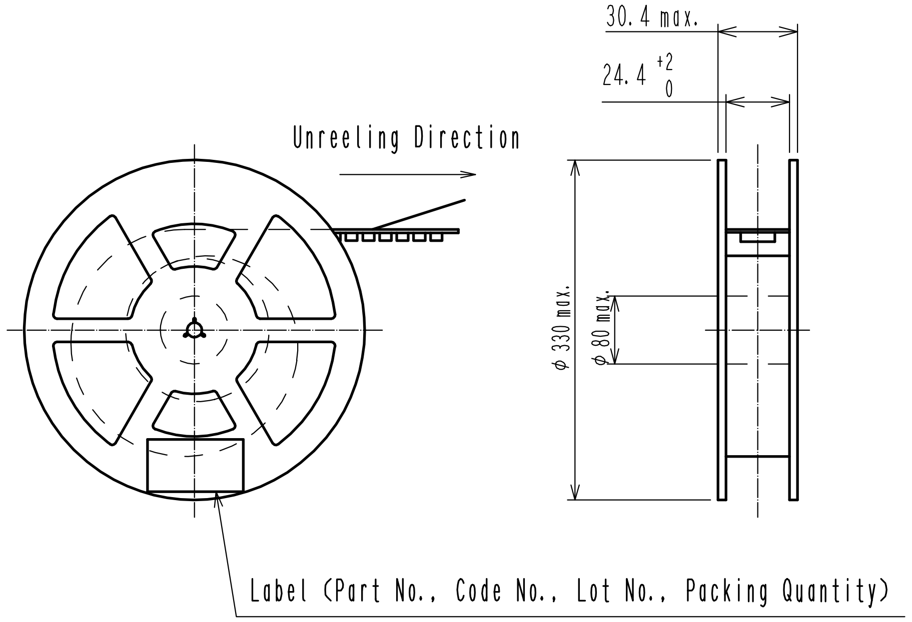


C-C



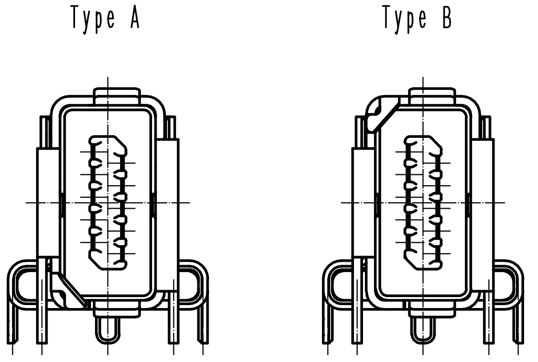
B-B



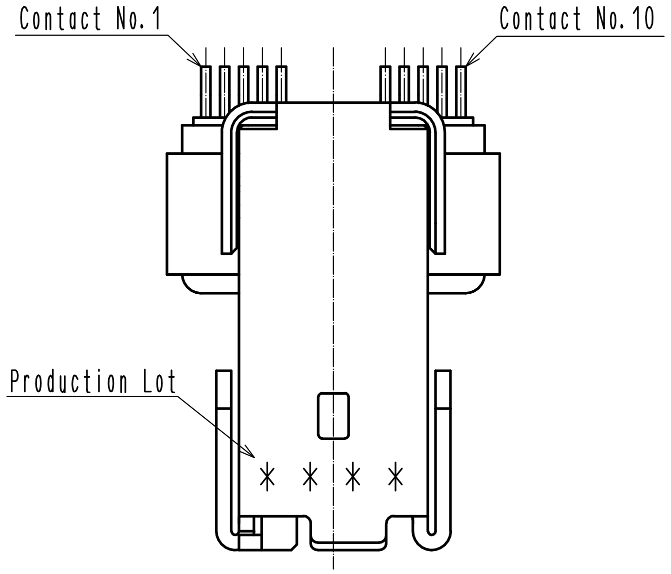


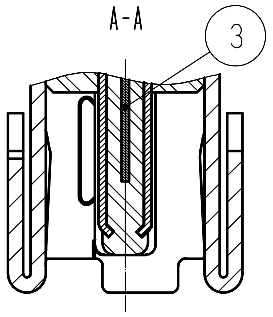
Notes 8. This product (Type B) is used for non Ethernet applications
like signaling, serial or other industrial bus communication systems.
Please use Type A for 10/100Mbit/s and 1/10 Gbit/s Ehernet communication.

Mating Shape


Type A
Type B

HRS	DRAWING NO.	EDC-129488-02-00
	PART NO.	IX61G-B-10P(02)
	CODE NO.	CL251-0026-0-02 △3 3/3





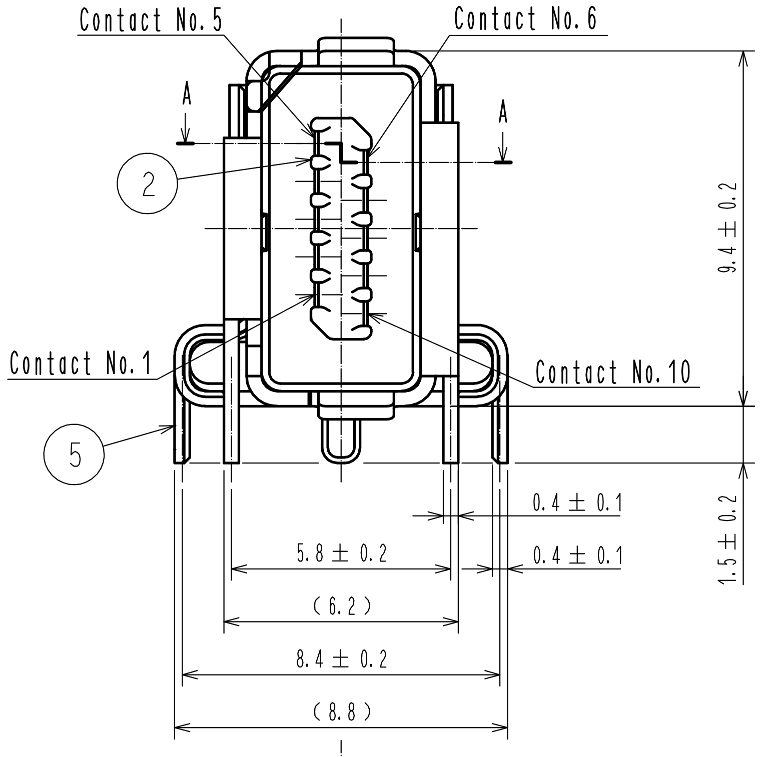
Notes. 1 Co-planarity is within 0.1 mm.

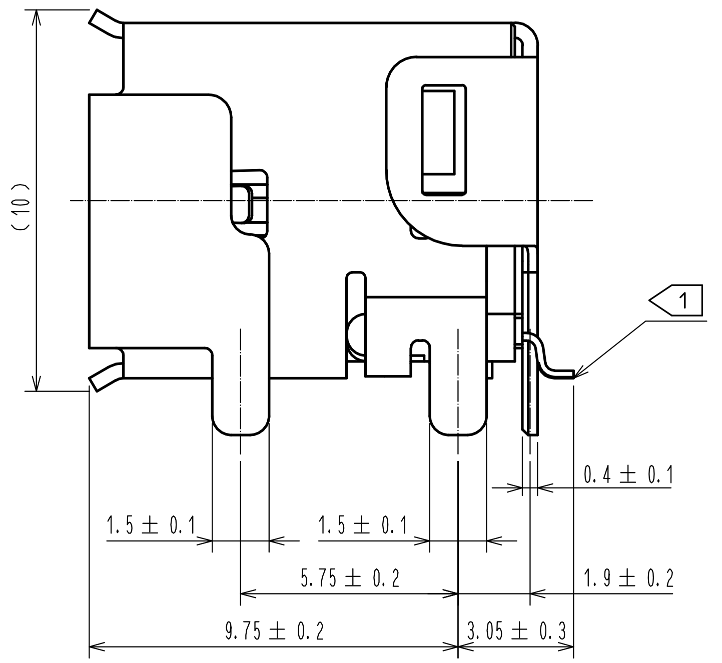
2. As for part No.5 the performance remains good even if there are rubbing wounds by the assembly process.
And the perfomance remains good though there might be a difference inthe pating luster betewen each plating lots.

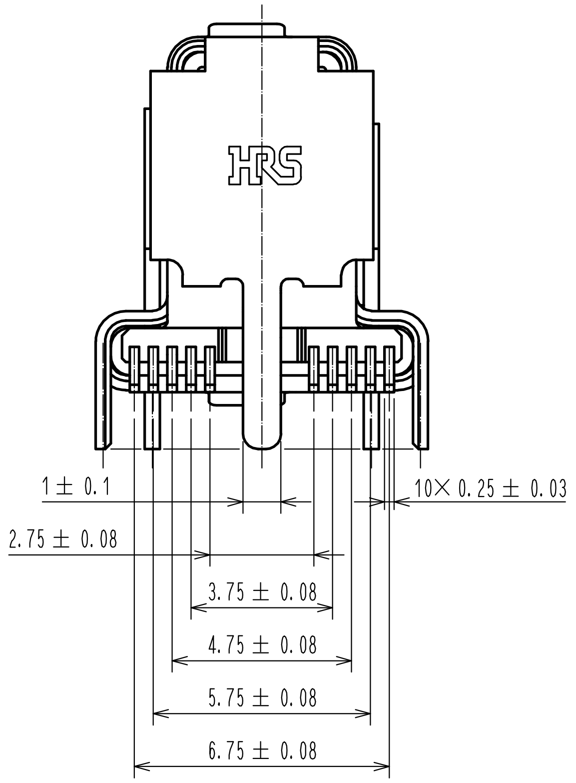
3 Per reel : 400 pcs.

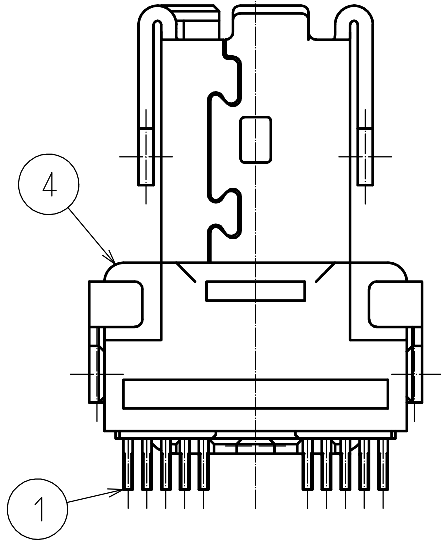
4 Refer to the mated condition diagram for the panel thickness and layout.

5. This produt is mounted by reflow soldering.
Refer to specification sheet ELC-129488-00-00 for reflow soldering.









NO.	MATERIAL	FINISH , REMARKS
3	Stainless Steel	
2	LCP	Gray、UL94V-0
1	Copper Alloy	Contact area :Gold 0.2 μm min. Lead area :Gold 0.03 μm min. Under plating :Nickel 2 μm min.

NO.	MATERIAL	FINISH , REMARKS
7	PE	
6	PS	
5	Stainless Steel	Surface : Tin 1 μm min. Under plating : Nickel 0.2 μm min.
4	LCP	Gray、UL94V-0

UNITS		SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm		5 : 1	5	1	DIS-E-00002758	MT. YASUDA	KI. NAGANUMA	20191219

HIROSE
ELECTRIC
CO., LTD.

APPROVED	:RI. TAKAYASU	20170328	DRAWING NO.	EDC-129488-00-00
CHECKED	:KI. NAGANUMA	20170327	PART NO.	IX61G-B-10P
DESIGNED	:TS. SAKAIZAWA	20170327	CODE NO.	CL251-0026-0-00
DRAWN	:TS. SAKAIZAWA	20170327		5 1/3

RoHS2(10 substances conformity)
参考図:ご確認用。正式には別途納入仕様書をご請求願います。
本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。

RoHS2(10 substances conformity)
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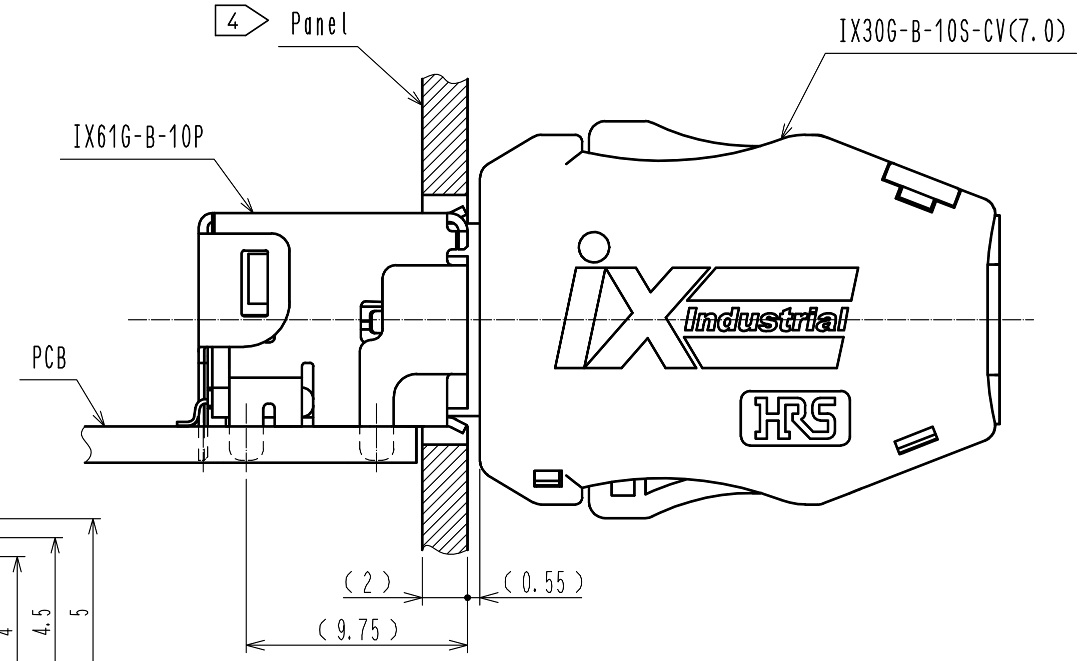
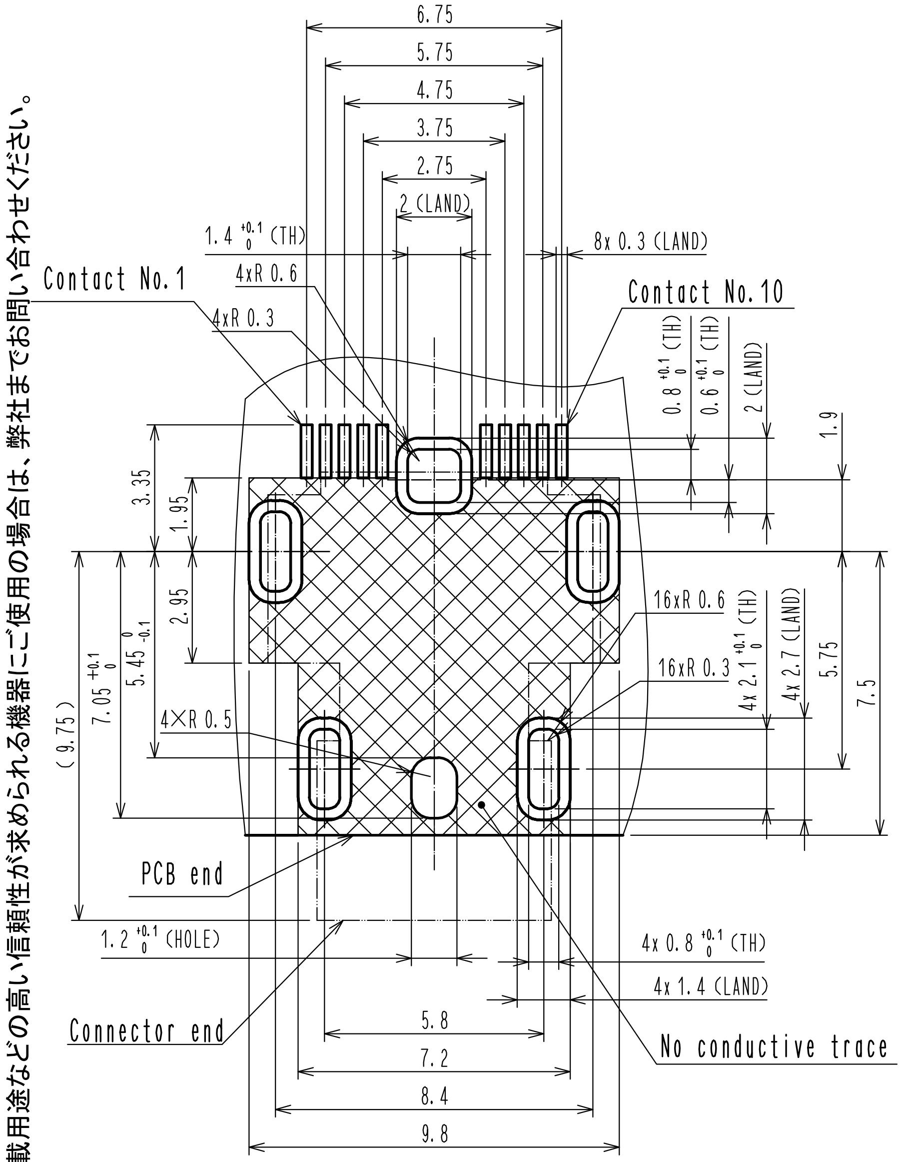
本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。

Mated Condition (Free)

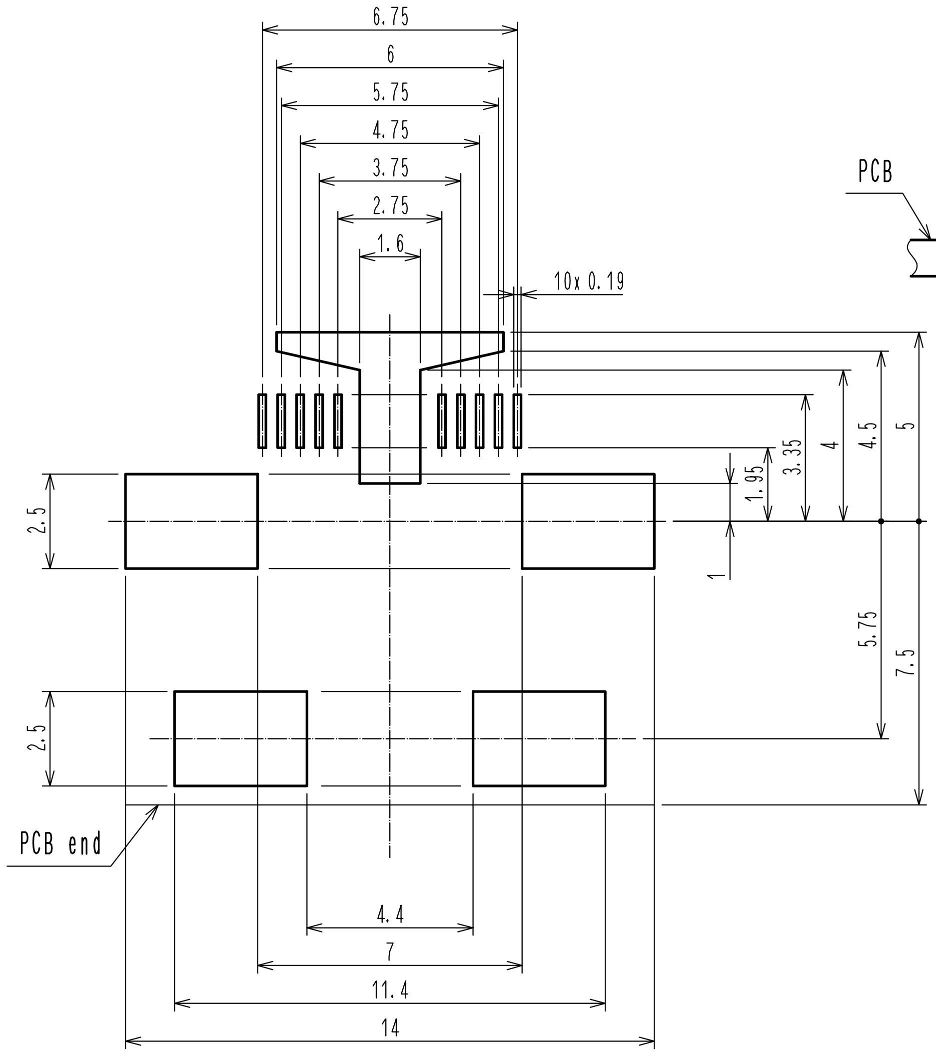


Reference PCB Layout (Connector Mounting Side) (t = 1.6)



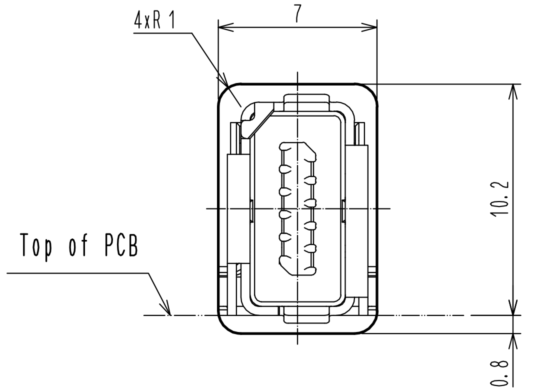
General tolerance is +/- 0.05

6 Reference Metal Mask Layout (t = 0.15)



General tolerance is +/- 0.02

4 Reference Dimensions of Panel Cutout (FREE)



Dimension is reference.

6 Thickness of metal mask is 0.1 mm min.
Metal mask dimensions of the drawings described, are reference dimensions for 0.15 mm thickness metal mask.
Change the metal mask dimensions by thickness of the metal mask, thickness of PCB, component of solder paste and mounting conditions.
Change the metal mask dimensions in case of mounting IX61G-*-10P in parallel.
Change the metal mask dimensions, if there are other mounting parts or implementation pattern around the portion of mounting position of IX61G-*-10P.
Refer to the technical specification (ETAD-E3170-00) for different variations of the metal mask pattern width.

HRS	DRAWING NO.	EDC-129488-00-00
	PART NO.	IX61G-B-10P
	CODE NO.	CL251-0026-0-00 5 2/3

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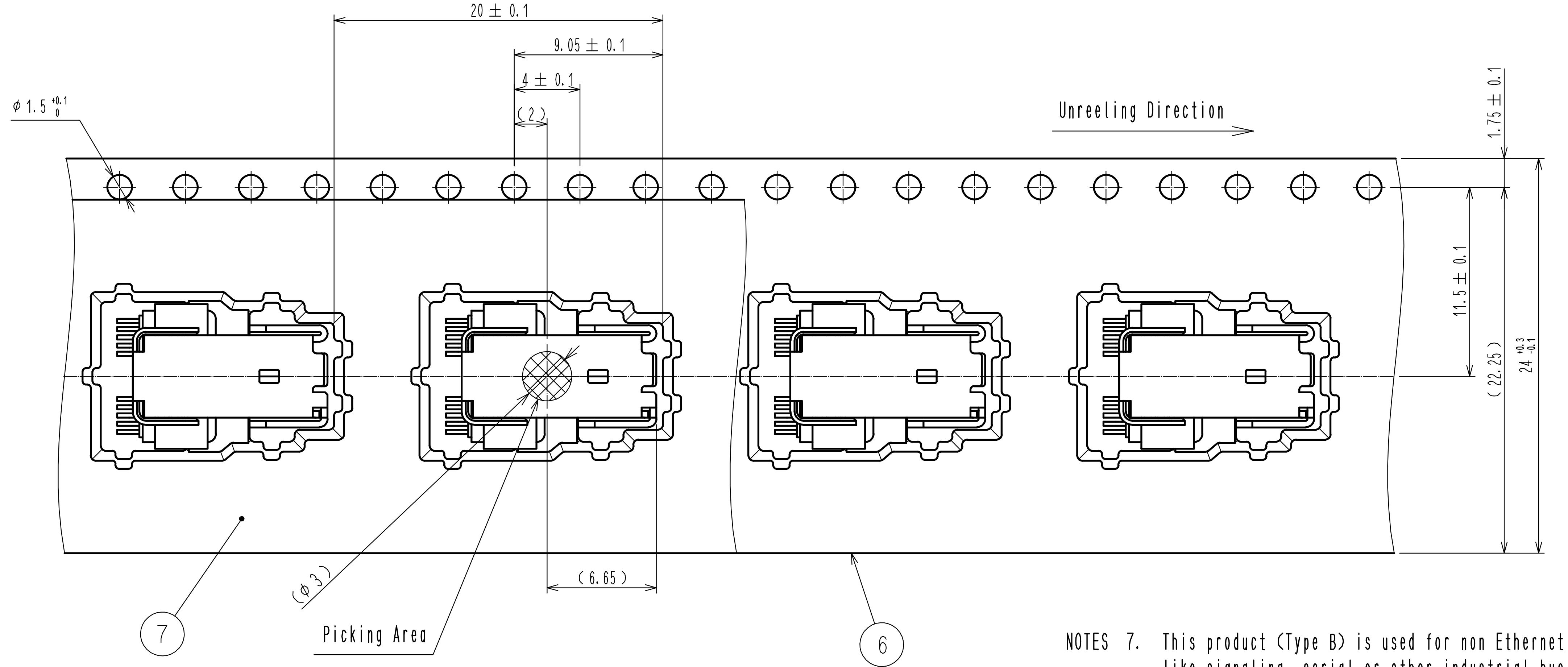
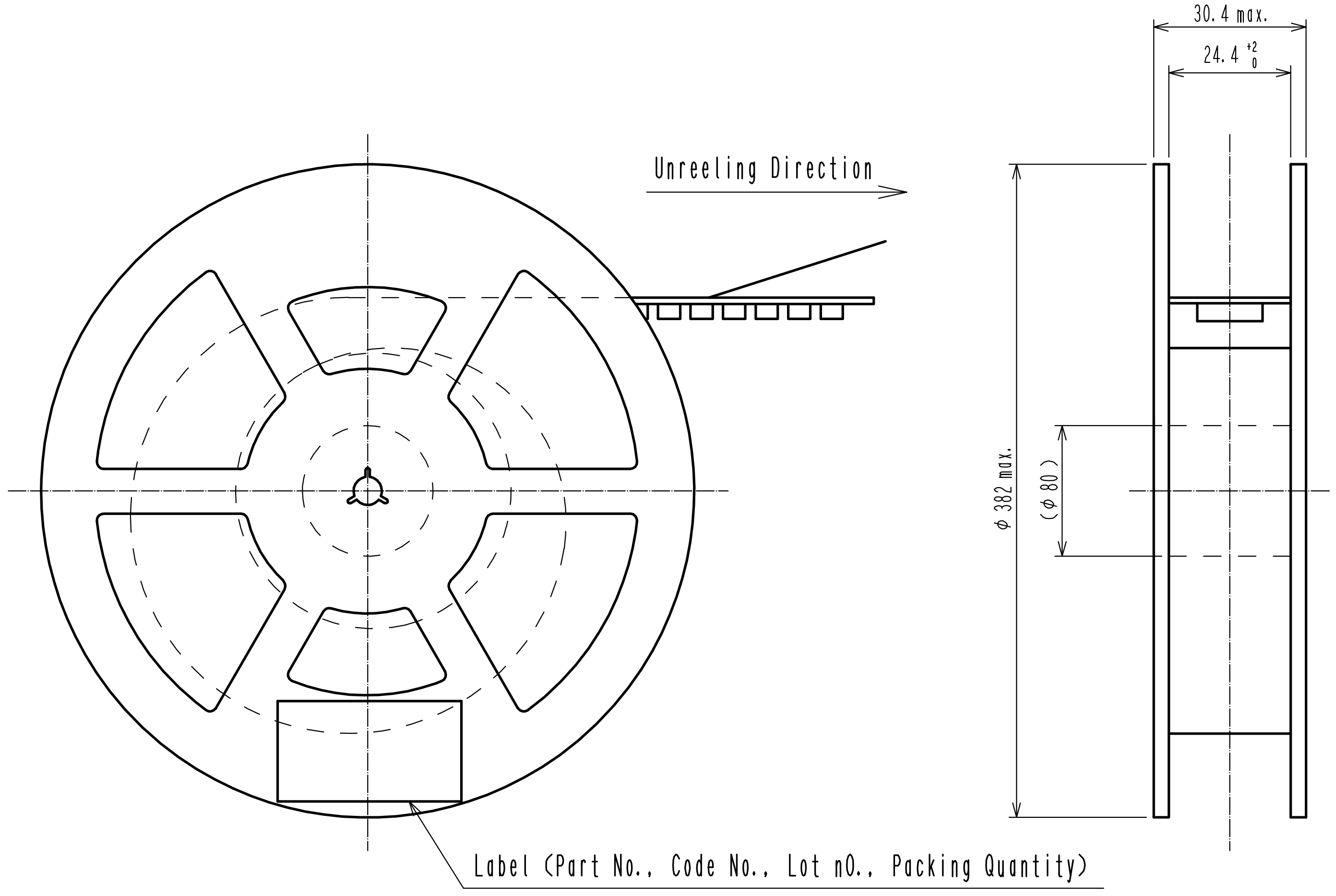
RoHS2(10 substances conformity)
参考図：ご確認用。正式には別途納入仕様書をご請求願います。
本製品を車載用途などの高い信頼性が求められる機器にご使用の場合は、弊社までお問い合わせください。

△5 3 Drawing for packing (Free)

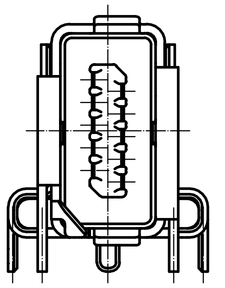


NOTES 7. This product (Type B) is used for non Ethernet applications
like signaling, serial or other industrial bus communication systems.
Please use Type A for 10/100Mbit/s and 1/10 Gbit/s Ethernet communication.

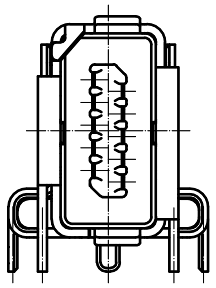


Mating Shape

Type A



Type B



DRAWING NO.	EDC-129488-00-00
PART NO.	IX61G-B-10P
CODE NO.	CL251-0026-0-00 △5 3/3

FORM HC0011-5-8